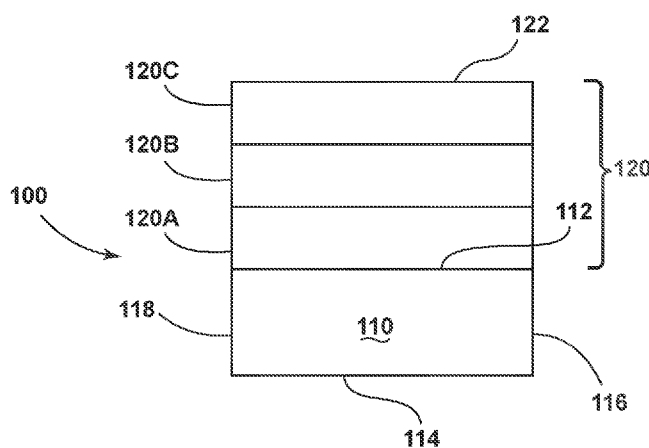


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METHODS OF MAKING THE SAME**FIG. 1**(57) Abstract: An optical film structure that includes: an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride. The optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film. Further, the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

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OPTICAL FILM STRUCTURES, INORGANIC OXIDE ARTICLES WITH OPTICAL FILM STRUCTURES, AND METHODS OF MAKING THE SAME

BACKGROUND

[0001] This application claims the benefit of priority under 35 U.S.C. § 119 of U.S. Provisional Application Serial No. 62/767,948, filed on November 15, 2018, the content of which is relied upon and incorporated herein by reference in its entirety.

[0002] The disclosure relates to optical film structures, optical film structures with thin, durable anti-reflective structures, and methods for making the same, and more particularly to optical film structures with thin, multi-layer anti-reflective coatings.

[0003] Cover articles are often used to protect devices within electronic products, to provide a user interface for input and/or display, and/or for many other functions. Such products include mobile devices, for example smart phones, smart watches, mp3 players and computer tablets. Cover articles also include architectural articles, transportation articles (e.g., interior and exterior display and non-display articles used in automotive applications, trains, aircraft, sea craft, etc.), appliance articles, or any article that may benefit from some transparency, scratch-resistance, abrasion resistance or a combination thereof. These applications often demand scratch-resistance and strong optical performance characteristics, in terms of maximum light transmittance and minimum reflectance. Furthermore, for some cover applications it is beneficial that the color exhibited or perceived, in reflection and/or transmission, does not change appreciably as the viewing angle is changed. In display applications, this is because, if the color in reflection or transmission changes with viewing angle to an appreciable degree, the user of the product will perceive a change in color or brightness of the display, which can diminish the perceived quality of the display. In other applications, changes in color may negatively impact the aesthetic appearance or other functional aspects of the device.

[0004] These display and non-display articles are often used in applications (e.g., mobile devices) with packaging constraints. In particular, many of these applications can significantly benefit from reductions in overall thickness, even reductions of a few percent. In addition, many of the applications that employ such display and non-display articles benefit from low manufacturing cost, e.g., through the minimization of raw material costs, minimization of

process complexity and yield improvements. Smaller packaging with optical and mechanical property performance attributes comparable to existing display and non-display articles can also serve the desire for reduced manufacturing cost (e.g., through less raw material costs, through reductions in the number of layers in an anti-reflective structure, etc.).

[0005] The optical performance of cover articles can be improved by using various anti-reflective coatings; however known anti-reflective coatings are susceptible to wear or abrasion. Such abrasion can compromise any optical performance improvements achieved by the anti-reflective coating. For example, optical filters are often made from multilayer coatings having differing refractive indices and made from optically transparent dielectric material (e.g., oxides, nitrides, and fluorides). Most of the typical oxides used for such optical filters are wide band-gap materials, which do not have the requisite mechanical properties, for example hardness, for use in mobile devices, architectural articles, transportation articles or appliance articles. Most nitrides and diamond-like coatings may exhibit high hardness values, which can be correlated to improved abrasion resistance, but such materials do not exhibit the desired transmittance for such applications.

[0006] Abrasion damage can include reciprocating sliding contact from counter face objects (e.g., fingers). In addition, abrasion damage can generate heat, which can degrade chemical bonds in the film materials and cause flaking and other types of damage to the cover glass. Since abrasion damage is often experienced over a longer term than the single events that cause scratches, the coating materials disposed experiencing abrasion damage can also oxidize, which further degrades the durability of the coating.

[0007] Accordingly, there is a need for new cover articles, and methods for their manufacture, which are abrasion resistant, have acceptable or improved optical performance and thinner optical film structures.

SUMMARY

[0008] According to some embodiments of the disclosure, an optical film structure is provided that includes: an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride. The optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack

comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film. Further, the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[0009] According to some embodiments of the disclosure, an optical article is provided that includes: an inorganic oxide substrate comprising opposing major surfaces; and an optical film structure disposed on a first major surface of the inorganic oxide substrate, the optical film structure comprising an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride. The optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film. Further, the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[0010] According to some embodiments of the disclosure, an optical article is provided that includes: an inorganic oxide substrate comprising opposing major surfaces; and an optical film structure disposed on a first major surface of the inorganic oxide substrate, the optical film structure comprising a plurality of optical films. Each optical film comprises a physical thickness from about 50 nm to about 3000 nm, and one of a silicon-containing oxide, a silicon-containing nitride and a silicon-containing oxynitride. Each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride. Further, each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[0011] According to some embodiments of the disclosure, a method of making an optical film structure is provided that includes: providing a substrate comprising opposing major surfaces within a sputtering chamber; sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride; and removing the optical film and the substrate from the chamber. The optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film. Further, the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[0012] Additional features and advantages will be set forth in the detailed description which follows, and in part will be readily apparent to those skilled in the art from that description or recognized by practicing the embodiments as described herein, including the detailed description which follows, the claims, as well as the appended drawings.

[0013] It is to be understood that both the foregoing general description and the following detailed description are merely exemplary, and are intended to provide an overview or framework to understanding the nature and character of the claims.

[0014] The accompanying drawings are included to provide a further understanding, and are incorporated in and constitute a part of this specification. The drawings illustrate one or more embodiment(s) and, together with the description, serve to explain, by way of example, principles and operation of the disclosure. It is to be understood that various features of the disclosure disclosed in this specification and in the drawings can be used in any and all combinations. By way of non-limiting examples, the various features of the disclosure may be combined with one another according to the following embodiments.

BRIEF DESCRIPTION OF THE DRAWINGS

[0015] These and other features, aspects and advantages of the present disclosure are better understood when the following detailed description of the disclosure is read with reference to the accompanying drawings, in which:

[0016] FIG. 1 is a side view of an article, according to one or more embodiments;

[0017] FIG. 2A is a side view of an article, according to one or more embodiments;

[0018] FIG. 2B is a side view of an article, according to one or more embodiments;

[0019] FIG. 2C is a side view of an article, according to one or more embodiments;

[0020] FIG. 3 is a side view of an article, according to one or more embodiments;

[0021] FIG. 4A is a plan view of an exemplary electronic device incorporating any of the articles disclosed herein;

[0022] FIG. 4B is a perspective view of the exemplary electronic device of FIG. 4A;

[0023] FIG. 5 is a perspective view of a vehicle interior with vehicular interior systems that may incorporate any of the articles disclosed herein;

[0024] FIG. 6 is a plot of hardness vs. indentation depth for articles disclosed herein;

[0025] FIG. 7 is a plot of first-surface, reflected color coordinates measured at, or calculated for, near-normal incidence of articles disclosed herein;

[0026] FIG. 8 is a plot of specular component excluded (SCE) values obtained from articles of the disclosure as subjected to the Alumina SCE Test and obtained from a comparative anti-reflective coating comprising niobia and silica; and

[0027] FIG. 9 is a plot of hardness vs. indentation depth for a hardness test stack of high refractive index layer material, according to an embodiment, that is suitable for use in the anti-reflective coatings and articles of the disclosure.

DETAILED DESCRIPTION

[0028] In the following detailed description, for purposes of explanation and not limitation, example embodiments disclosing specific details are set forth to provide a thorough understanding of various principles of the present disclosure. However, it will be apparent to one having ordinary skill in the art, having had the benefit of the present disclosure, that the present disclosure may be practiced in other embodiments that depart from the specific details

disclosed herein. Moreover, descriptions of well-known devices, methods and materials may be omitted so as not to obscure the description of various principles of the present disclosure.

Finally, wherever applicable, like reference numerals refer to like elements.

[0029] Ranges can be expressed herein as from “about” one particular value, and/or to “about” another particular value. As used herein, the term “about” means that amounts, sizes, formulations, parameters, and other quantities and characteristics are not and need not be exact, but may be approximate and/or larger or smaller, as desired, reflecting tolerances, conversion factors, rounding off, measurement error and the like, and other factors known to those of skill in the art. When the term “about” is used in describing a value or an end-point of a range, the disclosure should be understood to include the specific value or end-point referred to. Whether or not a numerical value or end-point of a range in the specification recites “about,” the numerical value or end-point of a range is intended to include two embodiments: one modified by “about,” and one not modified by “about.” It will be further understood that the endpoints of each of the ranges are significant both in relation to the other endpoint, and independently of the other endpoint.

[0030] The terms “substantial,” “substantially,” and variations thereof as used herein are intended to note that a described feature is equal or approximately equal to a value or description. For example, a “substantially planar” surface is intended to denote a surface that is planar or approximately planar. Moreover, “substantially” is intended to denote that two values are equal or approximately equal. In some embodiments, “substantially” may denote values within about 10% of each other, for example within about 5% of each other, or within about 2% of each other.

[0031] Directional terms as used herein – for example up, down, right, left, front, back, top, bottom – are made only with reference to the figures as drawn and are not intended to imply absolute orientation.

[0032] Unless otherwise expressly stated, it is in no way intended that any method set forth herein be construed as requiring that its steps be performed in a specific order. Accordingly, where a method claim does not actually recite an order to be followed by its steps, or it is not otherwise specifically stated in the claims or descriptions that the steps are to be limited to a specific order, it is in no way intended that an order be inferred, in any respect. This holds for any possible non-express basis for interpretation, including: matters of logic with respect to

arrangement of steps or operational flow; plain meaning derived from grammatical organization or punctuation; the number or type of embodiments described in the specification.

[0033] As used herein, the singular forms “a,” “an” and “the” include plural referents unless the context clearly dictates otherwise. Thus, for example, reference to a “component” includes embodiments having two or more such components, unless the context clearly indicates otherwise.

[0034] Embodiments of the disclosure relate to inorganic oxide articles with thin, durable anti-reflective structures and methods for making the same, and more particularly to articles with thin, multi-layer anti-reflective coatings exhibiting abrasion resistance, low reflectivity, and colorless transmittance and/or reflectance. Embodiments of these articles possess anti-reflective optical structures with a total physical thickness of less than 500 nm, while maintaining the hardness, abrasion resistance and optical properties associated with the intended applications for these articles (e.g., as covers, housings and substrates for display devices, interior and exterior automotive components, etc.). Further, some embodiments of these articles possess an optical film having a physical thickness from about 50 nm to about 3000 nm.

[0035] Referring to FIG. 1, the article 100 according to one or more embodiments may include a substrate 110, and an anti-reflective coating 120 (also referred herein as an “optical film structure”) disposed on the substrate. The substrate 110 includes opposing major surfaces 112, 114 and opposing minor surfaces 116, 118. The anti-reflective coating 120 is shown in FIG. 1 as being disposed on a first opposing major surface 112; however, the anti-reflective coating 120 may be disposed on the second opposing major surface 114 and/or one or both of the opposing minor surfaces, in addition to or instead of being disposed on the first opposing major surface 112. The anti-reflective coating 120 forms an anti-reflective surface 122.

[0036] Referring again to FIG. 1, the anti-reflective coating 120 includes at least one layer (also referred herein as an “optical film”) of at least one material, e.g., one or more of layers 120A, 120B and/or 120C. As such, according to some embodiments, the anti-reflective coating can include an optical film 120A, 120B or 120C, without additional layers (not shown). The terms “layer” and “film” may include a single layer or may include one or more sub-layers. Such sub-layers may be in direct contact with one another. The sub-layers may be formed from the same material or two or more different materials. In one or more alternative embodiments, such sub-layers may have intervening layers of different materials disposed therebetween. In one or

more embodiments a layer may include one or more contiguous and uninterrupted layers and/or one or more discontinuous and interrupted layers (i.e., a layer having different materials formed adjacent to one another). A layer or sub-layers may be formed by a discrete deposition or a continuous deposition process. In one or more embodiments, the layer may be formed using only continuous deposition processes, or, alternatively, only discrete deposition processes.

[0037] As used herein, the term “dispose” includes coating, depositing and/or forming a material onto a surface. The disposed material may constitute a layer, as defined herein. The phrase “disposed on” includes the instance of forming a material onto a surface such that the material is in direct contact with the surface and also includes the instance where the material is formed on a surface, with one or more intervening material(s) between the disposed material and the surface. The intervening material(s) may constitute a layer, as defined herein.

[0038] According to one or more embodiments, the anti-reflective coating 120 of the article 100 (e.g., as shown and described in connection with FIG. 1) can be characterized with abrasion resistance according to the Alumina SCE Test. As used herein, the “Alumina SCE Test” is conducted by subjecting a sample to a commercial 800 grit alumina sandpaper (10 mm x 10 mm) with a total weight of 0.7 kg for fifty (50) abrasion cycles, using an ~1” stroke length powered by a Taber Industries 5750 linear abrader. Abrasion resistance is then characterized, according to the Alumina SCE Test, by measuring reflected specular component excluded (SCE) values from the abraded samples according to principles understood by those with ordinary skill in the field of the disclosure. More particularly, SCE is a measure of diffuse reflection off of the surface of the anti-reflection coating 120, as measured using a Konica-Minolta CM700D with a 6 mm diameter aperture. According to some implementations, the anti-reflective coating 120 of the articles 100 can exhibit SCE values, as obtained from the Alumina SCE Test, of less than 0.4%, less than 0.2%, 0.18%, 0.16%, or even less than 0.08%. In contrast, commercial anti-reflection coatings (such as a six-layer $\text{Nb}_2\text{O}_5/\text{SiO}_2$ multilayer coating) have a post-sandpaper abrasion SCE value of greater than 0.6%. Abrasion-induced damage increases the surface roughness leading to the increase in diffuse reflection (i.e., SCE values). Lower SCE values indicates less severe damage, indicative of improved abrasion resistance.

[0039] The anti-reflective coating 120 and the article 100 may be described in terms of a hardness measured by a Berkovich Indenter Hardness Test. Further, those with ordinary skill in the art can recognize that abrasion resistance of the anti-reflective coating 120 and the article 100

can be correlated to the hardness of these elements. As used herein, the “Berkovich Indenter Hardness Test” includes measuring the hardness of a material on a surface thereof by indenting the surface with a diamond Berkovich indenter. The Berkovich Indenter Hardness Test includes indenting the anti-reflective surface 122 of the article 100 or the surface of the anti-reflective coating 120 (or the surface of any one or more of the layers in the anti-reflective coating) with the diamond Berkovich indenter to form an indent to an indentation depth in the range from about 50 nm to about 1000 nm (or the entire thickness of the anti-reflective coating or layer, whichever is less) and measuring the hardness from this indentation at various points along the entire indentation depth range, along a specified segment of this indentation depth (e.g., in the depth range from about 100 nm to about 500 nm), or at a particular indentation depth (e.g., at a depth of 100 nm, at a depth of 500 nm, etc.) generally using the methods set forth in Oliver, W.C.; Pharr, G. M. An improved technique for determining hardness and elastic modulus using load and displacement sensing indentation experiments. *See J. Mater. Res.*, Vol. 7, No. 6, 1992, 1564-1583; and Oliver, W.C. and Pharr, G.M, “Measurement of Hardness and Elastic Modulus by Instrument Indentation: Advances in Understanding and Refinements to Methodology”, *J. Mater. Res.*, Vol. 19, No. 1, 2004, 3-20. Further, when hardness is measured over an indentation depth range (e.g., in the depth range from about 100 nm to about 500 nm), the results can be reported as a maximum hardness within the specified range, wherein the maximum is selected from the measurements taken at each depth within that range. As used herein, “hardness” and “maximum hardness” both refer to as-measured hardness values, not averages of hardness values. Similarly, when hardness is measured at an indentation depth, the value of the hardness obtained from the Berkovich Indenter Hardness Test is given for that particular indentation depth.

[0040] Typically, in nanoindentation measurement methods (such as by using a Berkovich indenter) of a coating that is harder than the underlying substrate, the measured hardness may appear to increase initially due to development of the plastic zone at shallow indentation depths and then increases and reaches a maximum value or plateau at deeper indentation depths. Thereafter, hardness begins to decrease at even deeper indentation depths due to the effect of the underlying substrate. Where a substrate having an increased hardness compared to the coating is utilized, the same effect can be seen; however, the hardness increases at deeper indentation depths due to the effect of the underlying substrate.

[0041] The indentation depth range and the hardness values at certain indentation depth range(s) can be selected to identify a particular hardness response of the optical film structures and layers thereof, described herein, without the effect of the underlying substrate. When measuring hardness of the optical film structure (when disposed on a substrate) with a Berkovich indenter, the region of permanent deformation (plastic zone) of a material is associated with the hardness of the material. During indentation, an elastic stress field extends well beyond this region of permanent deformation. As indentation depth increases, the apparent hardness and modulus are influenced by stress field interactions with the underlying substrate. The substrate influence on hardness occurs at deeper indentation depths (i.e., typically at depths greater than about 10% of the optical film structure or layer thickness). Moreover, a further complication is that the hardness response utilizes a certain minimum load to develop full plasticity during the indentation process. Prior to that certain minimum load, the hardness shows a generally increasing trend.

[0042] At small indentation depths (which also may be characterized as small loads) (e.g., up to about 50 nm), the apparent hardness of a material appears to increase dramatically versus indentation depth. This small indentation depth regime does not represent a true metric of hardness but instead, reflects the development of the aforementioned plastic zone, which is related to the finite radius of curvature of the indenter. At intermediate indentation depths, the apparent hardness approaches maximum levels. At deeper indentation depths, the influence of the substrate becomes more pronounced as the indentation depths increase. Hardness may begin to drop dramatically once the indentation depth exceeds about 30% of the optical film structure thickness or the layer thickness.

[0043] As noted above, those with ordinary skill in the art can consider various test-related considerations in ensuring that the hardness and maximum hardness values of the coating 120 and article 100 obtained from the Berkovich Indenter Hardness Test are indicative of these elements, rather than being unduly influenced by the substrate 110, for example. Further, those with ordinary skill in the art can also recognize that the embodiments of the disclosure surprisingly demonstrate high hardness values associated with the anti-reflective coating 120 despite the relatively low thickness of the coating 120 (i.e., < 500 nm). Indeed, as evidenced by the Examples detailed below in subsequent sections, the hardness of the high RI layer(s) 130B (also referred herein as an optical film 130B) within an anti-reflective coating (see, e.g., FIGS.

2A, 2B and 2C), can significantly influence the overall hardness and maximum hardness of the anti-reflective coating 120 and article 100, despite the relatively low thickness values associated with these layers. This is surprising because of the above test-related considerations, which detail how measured hardness is directly influenced by the thickness of a coating, for example the anti-reflective coating 120. In general, as a coating (over a thicker substrate) is reduced in thickness, and as the volume of harder material (e.g., as compared to other layers within the coating having a lower hardness) in the coating decreases, it would be expected that the measured hardness of the coating will trend toward the hardness of the underlying substrate. Nevertheless, the articles 100 of the disclosure, as including the anti-reflective coating 120 (and as also exemplified by the Examples outlined in detail below), surprisingly exhibit significantly high hardness values in comparison to the underlying substrate, thus demonstrating a unique combination of coating thickness (< 500 nm), volumetric fraction of higher hardness material and optical properties.

[0044] In some embodiments, the anti-reflective coating 120 of the article 100 may exhibit a hardness of greater than about 8 GPa, as measured on the anti-reflective surface 122, by a Berkovich Indenter Hardness Test at an indentation depth of about 100 nm. The antireflective coating 120 may exhibit a hardness of about 8 GPa or greater, about 9 GPa or greater, about 10 GPa or greater, about 11 GPa or greater, about 12 GPa or greater, about 13 GPa or greater, about 14 GPa or greater, or about 15 GPa or greater by a Berkovich Indenter Hardness Test at an indentation depth of about 100 nm. The article 100, including the anti-reflective coating 120 and any additional coatings, as described herein, may exhibit a hardness of about 8 GPa or greater, about 10 GPa or greater, about 12 GPa or greater, about 14 GPa or greater, or about 16 GPa or greater, as measured on the anti-reflective surface 122, by a Berkovich Indenter Hardness Test at an indentation depth of about 100 nm. Such measured hardness values may be exhibited by the anti-reflective coating 120 and/or the article 100 over an indentation depth of about 50 nm or greater or about 100 nm or greater (e.g., from about 100 nm to about 300 nm, from about 100 nm to about 400 nm, from about 100 nm to about 500 nm, from about 100 nm to about 600 nm, from about 200 nm to about 300 nm, from about 200 nm to about 400 nm, from about 200 nm to about 500 nm, or from about 200 nm to about 600 nm). Similarly, maximum hardness values of about 8 GPa or greater, about 9 GPa or greater, about 10 GPa or greater, about 11 GPa or greater, about 12 GPa or greater, about 13 GPa or greater, about 14 GPa or greater, about 15 GPa or greater, or

about 16 GPa or greater, by a Berkovich Indenter Hardness Test may be exhibited by the anti-reflective coating and/or the article over an indentation depth of about 50 nm or greater or about 100 nm or greater (e.g., from about 100 nm to about 300 nm, from about 100 nm to about 400 nm, from about 100 nm to about 500 nm, from about 100 nm to about 600 nm, from about 200 nm to about 300 nm, from about 200 nm to about 400 nm, from about 200 nm to about 500 nm, or from about 200 nm to about 600 nm).

[0045] The anti-reflective coating 120 may have at least one layer or film made of material itself having a maximum hardness (as measured on the surface of such a layer, e.g., a surface of the second high RI layer 130B of FIG. 2A) of about 18 GPa or greater, about 19 GPa or greater, about 20 GPa or greater, about 21 GPa or greater, about 22 GPa or greater, about 23 GPa or greater, about 24 GPa or greater, about 25 GPa or greater, and all hardness values therebetween, as measured by the Berkovich Indenter Hardness Test over an indentation depth from about 100 nm to about 500 nm. These measurements are made on a hardness test stack comprising the designated layer (e.g., a high RI layer 130B or an optical film 130B) of the anti-reflective coating 120 at a physical thickness of about 2 microns, as disposed on a substrate 110, to minimize the thickness-related hardness measurement effects described earlier. The maximum hardness of such a layer may be in the range from about 18 GPa to about 26 GPa, as measured by the Berkovich Indenter Hardness Test over an indentation depth from about 100 nm to about 500 nm. Such maximum hardness values may be exhibited by the material of at least one layer (e.g., the high RI layer(s) 130B, as shown in FIG. 2A) over an indentation depth of about 50 nm or greater or 100 nm or greater (e.g., from about 100 nm to about 300 nm, from about 100 nm to about 400 nm, from about 100 nm to about 500 nm, from about 100 nm to about 600 nm, from about 200 nm to about 300 nm, from about 200 nm to about 400 nm, from about 200 nm to about 500 nm, or from about 200 nm to about 600 nm). In one or more embodiments, the article 100 exhibits a hardness that is greater than the hardness of the substrate (which can be measured on the opposite surface from the anti-reflective surface). Similarly, hardness values may be exhibited by the material of at least one layer (e.g., the high RI layer(s) 130B, as shown in FIG. 2A) over an indentation depth of about 50 nm or greater or about 100 nm or greater (e.g., from about 100 nm to about 300 nm, from about 100 nm to about 400 nm, from about 100 nm to about 500 nm, from about 100 nm to about 600 nm, from about 200 nm to about 300 nm, from about 200 nm to about 400 nm, from about 200 nm to about 500 nm, or from about 200 nm to about

600 nm). In addition, these hardness and/or maximum hardness values associated with the at least one layer (e.g., the high RI layer(s) 130B) can also be observed at particular indentation depths (e.g., at 100 nm, 200 nm, etc.) over the measured indentation depth ranges. Further, according to some implementations, at least one layer or optical film (e.g., a high RI layer 130B) of the anti-reflective coating 120 can have a physical thickness that ranges from about 50 nm to about 3000 nm.

[0046] Optical interference between reflected waves from the interface between the anti-reflective coating 120 and air, and from the interface between the anti-reflective coating 120 and substrate 110, can lead to spectral reflectance and/or transmittance oscillations that create apparent color in the article 100. As used herein, the term “transmittance” is defined as the percentage of incident optical power within a given wavelength range transmitted through a material (e.g., the article, the substrate or the optical film or portions thereof). The term “reflectance” is similarly defined as the percentage of incident optical power within a given wavelength range that is reflected from a material (e.g., the article, the substrate, or the optical film or portions thereof). In one or more embodiments, the spectral resolution of the characterization of the transmittance and reflectance is less than 5 nm or 0.02 eV. The color may be more pronounced in reflection. The angular color shifts in reflection with viewing angle due to a shift in the spectral reflectance oscillations with incident illumination angle. Angular color shifts in transmittance with viewing angle are also due to the same shift in the spectral transmittance oscillation with incident illumination angle. The observed color and angular color shifts with incident illumination angle are often distracting or objectionable to device users, particularly under illumination with sharp spectral features for example fluorescent lighting and some LED lighting. Angular color shifts in transmission may also play a factor in angular color shift in reflection and vice versa. Factors in angular color shifts in transmission and/or reflection may also include angular color shifts due to viewing angle or color shifts away from a certain white point that may be caused by material absorption (somewhat independent of angle) defined by a particular illuminant or test system.

[0047] The oscillations may be described in terms of amplitude. As used herein, the term “amplitude” includes the peak-to-valley change in reflectance or transmittance. The phrase “average amplitude” includes the peak-to-valley change in reflectance or transmittance averaged within the optical wavelength regime. As used herein, the “optical

wavelength regime” includes the wavelength range from about 400 nm to about 800 nm (and more specifically from about 450 nm to about 650 nm).

[0048] The embodiments of this disclosure include an anti-reflective coating (e.g., anti-reflective coating 120 or optical film structure 120) to provide improved optical performance, in terms of colorlessness and/or smaller angular color shifts when viewed at varying incident illumination angles from normal incidence under different illuminants.

[0049] One aspect of this disclosure pertains to an article that exhibits colorlessness in reflectance and/or transmittance even when viewed at different incident illumination angles under an illuminant. In one or more embodiments, the article exhibits an angular color shift in reflectance and/or transmittance of about 5 or less, or about 2 or less, between a reference illumination angle and any incidental illumination angles, in the ranges provided herein. As used herein, the phrase “color shift” (angular or reference point) refers to the change in both a^* and b^* , under the CIE L^* , a^* , b^* colorimetry system in reflectance and/or transmittance. It should be understood that unless otherwise noted, the L^* coordinate of the articles described herein are the same at any angle or reference point and do not influence color shift. For example, angular color shift may be determined using the following Equation (1):

$$(1) \quad \sqrt{((a^*_2 - a^*_1)^2 + (b^*_2 - b^*_1)^2)}$$

with a^*_1 , and b^*_1 representing the a^* and b^* coordinates of the article when viewed at a reference illumination angle (which may include normal incidence) and a^*_2 , and b^*_2 representing the a^* and b^* coordinates of the article when viewed at an incident illumination angle, provided that the incident illumination angle is different from reference illumination angle and in some cases differs from the reference illumination angle by about 1 degree or more, 2 degrees or more, or about 5 degrees or more, or about 10 degrees or more, or about 15 degrees or more, or about 20 degrees or more. In some instances, an angular color shift in reflectance and/or transmittance of about 10 or less (e.g., 5 or less, 4 or less, 3 or less, or 2 or less) is exhibited by the article when viewed at various incident illumination angles from a reference illumination angle, under an illuminant. In some instances the angular color shift in reflectance and/or transmittance is about 1.9 or less, 1.8 or less, 1.7 or less, 1.6 or less, 1.5 or less, 1.4 or less, 1.3 or less, 1.2 or less, 1.1 or less, 1 or less, 0.9 or less, 0.8 or less, 0.7 or less, 0.6 or less, 0.5 or less, 0.4 or less, 0.3 or less,

0.2 or less, or 0.1 or less. In some embodiments, the angular color shift may be about 0. The illuminant can include standard illuminants as determined by the CIE, including A illuminants (representing tungsten-filament lighting), B illuminants (daylight simulating illuminants), C illuminants (daylight simulating illuminants), D series illuminants (representing natural daylight), and F series illuminants (representing various types of fluorescent lighting). In specific examples, the articles exhibit an angular color shift in reflectance and/or transmittance of about 2 or less when viewed at incident illumination angle from the reference illumination angle under a CIE F2, F10, F11, F12 or D65 illuminant or more specifically under a CIE F2 illuminant.

[0050] The reference illumination angle may include normal incidence (i.e., 0 degrees), or 5 degrees from normal incidence, 10 degrees from normal incidence, 15 degrees from normal incidence, 20 degrees from normal incidence, 25 degrees from normal incidence, 30 degrees from normal incidence, 35 degrees from normal incidence, 40 degrees from normal incidence, 50 degrees from normal incidence, 55 degrees from normal incidence, or 60 degrees from normal incidence, provided the difference between the reference illumination angle and the difference between the incident illumination angle and the reference illumination angle is about 1 degree or more, 2 degrees or more, or about 5 degrees or more, or about 10 degrees or more, or about 15 degrees or more, or about 20 degrees or more. The incident illumination angle may be, with respect to the reference illumination angle, in the range from about 5 degrees to about 80 degrees, from about 5 degrees to about 70 degrees, from about 5 degrees to about 65 degrees, from about 5 degrees to about 60 degrees, from about 5 degrees to about 55 degrees, from about 5 degrees to about 50 degrees, from about 5 degrees to about 45 degrees, from about 5 degrees to about 40 degrees, from about 5 degrees to about 35 degrees, from about 5 degrees to about 30 degrees, from about 5 degrees to about 25 degrees, from about 5 degrees to about 20 degrees, from about 5 degrees to about 15 degrees, and all ranges and sub-ranges therebetween, away from normal incidence. The article may exhibit the angular color shifts in reflectance and/or transmittance described herein at and along all the incident illumination angles in the range from about 2 degrees to about 80 degrees, or from about 5 degrees to about 80 degrees, or from about 10 degrees to about 80 degrees, or from about 15 degrees to about 80 degrees, or from about 20 degrees to about 80 degrees, when the reference illumination angle is normal incidence. In some embodiments, the article may exhibit the angular color shifts in reflectance and/or transmittance described herein at and along all the incident illumination angles in the range from about 2

degrees to about 80 degrees, or from about 5 degrees to about 80 degrees, or from about 10 degrees to about 80 degrees, or from about 15 degrees to about 80 degrees, or from about 20 degrees to about 80 degrees, when the difference between the incident illumination angle and the reference illumination angle is about 1 degree or more, 2 degrees or more, or about 5 degrees or more, or about 10 degrees or more, or about 15 degrees or more, or about 20 degrees or more. In one example, the article may exhibit an angular color shift in reflectance and/or transmittance of 2 or less at any incident illumination angle in the range from about 2 degrees to about 60 degrees, from about 5 degrees to about 60 degrees, or from about 10 degrees to about 60 degrees away from a reference illumination angle equal to normal incidence. In other examples, the article may exhibit an angular color shift in reflectance and/or transmittance of 2 or less when the reference illumination angle is 10 degrees and the incident illumination angle is any angle in the range from about 12 degrees to about 60 degrees, from about 15 degrees to about 60 degrees, or from about 20 degrees to about 60 degrees away from the reference illumination angle.

[0051] In some embodiments, the angular color shift may be measured at all angles between a reference illumination angle (e.g., normal incidence) and an incident illumination angle in the range from about 20 degrees to about 80 degrees. In other words, the angular color shift may be measured and may be less than about 5, or less than about 2, at all angles in the range from about 0 degrees to about 20 degrees, from about 0 degrees to about 30 degrees, from about 0 degrees to about 40 degrees, from about 0 degrees to about 50 degrees, from about 0 degrees to about 60 degrees or from about 0 degrees to about 80 degrees.

[0052] In one or more embodiments, the article 100 exhibits a color in the CIE L^* , a^* , b^* colorimetry system in reflectance and/or transmittance such that the distance or reference point color shift between the transmittance color or reflectance coordinates from a reference point is less than about 5, or less than about 2, under an illuminant (which can include standard illuminants as determined by the CIE, including A illuminants (representing tungsten-filament lighting), B illuminants (daylight simulating illuminants), C illuminants (daylight simulating illuminants), D series illuminants (representing natural daylight), and F series illuminants (representing various types of fluorescent lighting)). In specific examples, the articles exhibit a color shift in reflectance and/or transmittance of about 2 or less when viewed at incident illumination angle from the reference illumination angle under a CIE F2, F10, F11, F12 or D65 illuminant or more specifically under a CIE F2 illuminant. Stated another way, the article may

exhibit a transmittance color (or transmittance color coordinates) and/or a reflectance color (or reflectance color coordinates) measured at the anti-reflective surface 122 having a reference point color shift of less than about 2 from a reference point, as defined herein. Unless otherwise noted, the transmittance color or transmittance color coordinates are measured on two surfaces of the article including at the anti-reflective surface 122 and the opposite bare surface of the article (i.e., 114). Unless otherwise noted, the reflectance color or reflectance color coordinates are measured on only the anti-reflective surface 122 of the article.

[0053] In one or more embodiments, the reference point may be the origin (0, 0) in the CIE L^* , a^* , b^* colorimetry system (or the color coordinates $a^*=0$, $b^*=0$), color coordinates (-2, -2) or the transmittance or reflectance color coordinates of the substrate. It should be understood that unless otherwise noted, the L^* coordinate of the articles described herein are the same as the reference point and do not influence color shift. Where the reference point color shift of the article is defined with respect to the substrate, the transmittance color coordinates of the article are compared to the transmittance color coordinates of the substrate and the reflectance color coordinates of the article are compared to the reflectance color coordinates of the substrate.

[0054] In one or more specific embodiments, the reference point color shift of the transmittance color and/or the reflectance color may be less than 1 or even less than 0.5. In one or more specific embodiments, the reference point color shift for the transmittance color and/or the reflectance color may be 1.8, 1.6, 1.4, 1.2, 0.8, 0.6, 0.4, 0.2, 0 and all ranges and sub-ranges therebetween. Where the reference point is the color coordinates $a^*=0$, $b^*=0$, the reference point color shift is calculated by Equation (2):

$$(2) \quad \text{reference point color shift} = \sqrt{((a^*_{\text{article}})^2 + (b^*_{\text{article}})^2)}.$$

Where the reference point is the color coordinates $a^*=-2$, $b^*=-2$, the reference point color shift is calculated by Equation (3):

$$(3) \quad \text{reference point color shift} = \sqrt{((a^*_{\text{article}} + 2)^2 + (b^*_{\text{article}} + 2)^2)}.$$

Where the reference point is the color coordinates of the substrate, the reference point color shift is calculated by Equation (4):

$$(4) \quad \text{reference point color shift} = \sqrt{((a^*_{\text{article}} - a^*_{\text{substrate}})^2 + (b^*_{\text{article}} - b^*_{\text{substrate}})^2)}.$$

[0055] In some embodiments, the article 100 may exhibit a transmittance color (or transmittance color coordinates) and a reflectance color (or reflectance color coordinates) such that the reference point color shift is less than 2 when the reference point is any one of the color coordinates of the substrate, the color coordinates $a^*=0$, $b^*=0$ and the coordinates $a^*=-2$, $b^*=-2$.

[0056] In some embodiments, the article 100 may exhibit a b^* value in reflectance (as measured at the anti-reflective surface 122 only) in the range from about -10 to about +2, from about -7 to about 0, from about -6 to about -1, from about -6 to about 0, or from about -4 to about 0, in the CIE L^* , a^* , b^* colorimetry system at a near-normal incident angle (i.e., at about 0 degrees, or within 10 degrees of normal). In other implementations, the article 100 may exhibit a b^* value in reflectance (as measured at the anti-reflective surface 122 only) in the range from about -10 to about +10, from about -10 to +2, from about -8 to about +8, or from about -5 to about +5, in the CIE L^* , a^* , b^* colorimetry system at all incidence illumination angles, including near-normal, in the range from about 0 to about 60 degrees (or from about 0 degrees to about 40 degrees, or from about 0 degrees to about 30 degrees).

[0057] In some embodiments, the article 100 may exhibit a b^* value in transmittance (as measured at the anti-reflective surface and the opposite bare surface of the article) in the range from about -2 to about +2, from about -1 to about +2, from about -0.5 to about +2, from about 0 to about +2, from about 0 to about +1, from about -2 to about +0.5, from about -2 to about +1, from about -1 to about +1, or from about 0 to about +0.5, in the CIE L^* , a^* , b^* colorimetry system at a near-normal incident angle (i.e., at about 0 degrees, or within 10 degrees of normal). In other implementations, the article may exhibit a b^* value in transmittance in the range from about -2 to about +2, from about -1 to about +2, from about -0.5 to about +2, from about 0 to about +2, from about 0 to about +1, from about -2 to about +0.5, from about -2 to about +1, from about -1 to about +1, or from about 0 to about +0.5, in the CIE L^* , a^* , b^* colorimetry system for all incidence illumination angles, including near-normal, in the range from about 0 to about 60 degrees (or from about 0 degrees to about 40 degrees, or from about 0 degrees to about 30 degrees).

[0058] In some embodiments, the article 100 may exhibit an a^* value in transmittance (as measured at the anti-reflective surface and the opposite bare surface of the article) in the range from about -2 to about +2, from about -1 to about +2, from about -0.5 to about +2, from about 0 to about +2, from about 0 to about +1, from about -2 to about +0.5, from about -2 to about +1, from about -1 to about +1, or from about 0 to about +0.5, in the CIE L^* , a^* , b^* colorimetry system at a near-normal incident angle (i.e., at about 0 degrees, or within 10 degrees of normal). In other implementations, the article may exhibit an a^* value in transmittance in the range from about -2 to about +2, from about -1 to about +2, from about -0.5 to about +2, from about 0 to about +2, from about 0 to about +1, from about -2 to about +0.5, from about -2 to about +1, from about -1 to about +1, or from about 0 to about +0.5, in the CIE L^* , a^* , b^* colorimetry system for all incidence illumination angles in the range from about 0 to about 60 degrees (or from about 0 degrees to about 40 degrees or from about 0 degrees to about 30 degrees).

[0059] In some embodiments, the article exhibits an a^* and/or b^* value in transmittance (at the anti-reflective surface and the opposite bare surface) in the range from about -1.5 to about +1.5 (e.g., -1.5 to -1.2, -1.5 to -1, -1.2 to +1.2, -1 to +1, -1 to +0.5, or -1 to 0) at incident illumination angles in the range from about 0 degrees to about 60 degrees under illuminants D65, A, and F2.

[0060] In some embodiments, the article 100 exhibits an a^* value in reflectance (at only the anti-reflective surface) in the range from about -10 to about +5, -5 to about +5 (e.g., -4.5 to +4.5, -4.5 to +1.5, -3 to 0, -2.5 to -0.25), or from about -4 to +4, at a near-normal incident angle (i.e., at about 0 degrees, or within 10 degrees of normal) in the CIE L^* , a^* , b^* colorimetry system. In other embodiments, the article 100 exhibits an a^* value in reflectance (at only the anti-reflective surface) in the range from about -5 to about +15 (e.g., -4.5 to +14) or from about -3 to +13 at incident illumination angles in the range from about 0 degrees to about 60 degrees in the CIE L^* , a^* , b^* colorimetry system.

[0061] The article 100 of one or more embodiments, or the anti-reflective surface 122 of one or more articles, may exhibit a photopic average light transmittance of about 94% or greater (e.g., about 94% or greater, about 95% or greater, about 96% or greater, about 96.5% or greater, about 97% or greater, about 97.5% or greater, about 98% or greater, about 98.5% or greater or about 99% or greater) over the optical wavelength regime in the range from about 400 nm to about 800 nm. In some embodiments, the article 100, or the anti-reflective surface 122 of one or more articles, may exhibit an average light reflectance of about 2% or less (e.g., about 1.5% or

less, about 1% or less, about 0.75% or less, about 0.5% or less, or about 0.25% or less) over the optical wavelength regime in the range from about 400 nm to about 800 nm. These light transmittance and light reflectance values may be observed over the entire optical wavelength regime or over selected ranges of the optical wavelength regime (e.g., a 100 nm wavelength range, 150 nm wavelength range, a 200 nm wavelength range, a 250 nm wavelength range, a 280 nm wavelength range, or a 300 nm wavelength range, within the optical wavelength regime). In some embodiments, these light reflectance and transmittance values may be a total reflectance or total transmittance (taking into account reflectance or transmittance on both the anti-reflective surface 122 and the opposite major surfaces, 114). Unless otherwise specified, the average reflectance or transmittance is measured at an incident illumination angle of 0 degrees (however, such measurements may be provided at incident illumination angles of 45 degrees or 60 degrees).

[0062] In some embodiments, the article 100 of one or more embodiments, the anti-reflective surface 122 of one or more articles, or an additional coating 140 in the form of an anti-reflective layer (see FIG. 3), may exhibit a visible photopic average reflectance of about 1% or less, about 0.9% or less, about 0.8% or less, about 0.7% or less, about 0.6% or less, about 0.5% or less, about 0.4% or less, about 0.3% or less, or about 0.2% or less, over the optical wavelength regime. These photopic average reflectance values may be exhibited at incident illumination angles in the range from about 0° to about 20°, from about 0° to about 40°, or from about 0° to about 60°. As used herein, “photopic average reflectance” mimics the response of the human eye by weighting the reflectance versus wavelength spectrum according to the human eye’s sensitivity. Photopic average reflectance may also be defined as the luminance, or tristimulus Y value of reflected light, according to known conventions for example CIE color space conventions. The photopic average reflectance is defined in Equation (5) as the spectral reflectance, $R(\lambda)$ multiplied by the illuminant spectrum, $I(\lambda)$ and the CIE’s color matching function $\bar{y}(\lambda)$, related to the eye’s spectral response:

$$(5) \quad \langle R_p \rangle = \int_{380\text{ nm}}^{720\text{ nm}} R(\lambda) \times I(\lambda) \times \bar{y}(\lambda) d\lambda .$$

[0063] In some embodiments, the anti-reflective surface 122 of one or more articles (i.e., when measuring the anti-reflective surface 122 only through a single-sided measurement), may exhibit a visible photopic average reflectance of about 2% or less, 1.8% or less, 1.5% or less, 1.2% or less, 1% or less, 0.9% or less, 0.7% or less, about 0.5% or less, about 0.45% or less, about 0.4% or less, about 0.35% or less, about 0.3% or less, about 0.25% or less, or about 0.2% or less. In such “single-sided” measurements as described in this disclosure, the reflectance from the second major surface (e.g., surface 114 shown in FIG. 1) is removed by coupling this surface to an index-matched absorber. In some cases, the visible photopic average reflectance ranges are exhibited while simultaneously exhibiting a maximum reflectance color shift, over the entire incident illumination angle range from about 5 degrees to about 60 degrees (with the reference illumination angle being normal incidence) using D65 illumination, of less than about 5.0, less than about 4.0, less than about 3.0, less than about 2.0, less than about 1.5, or less than about 1.25. These maximum reflectance color shift values represent the lowest color point value measured at any angle from about 5 degrees to about 60 degrees from normal incidence, subtracted from the highest color point value measured at any angle in the same range. The values may represent a maximum change in a^* value ($a^*_{\text{highest}} - a^*_{\text{lowest}}$), a maximum change in b^* value ($b^*_{\text{highest}} - b^*_{\text{lowest}}$), a maximum change in both a^* and b^* values, or a maximum change in the quantity $\sqrt{((a^*_{\text{highest}} - a^*_{\text{lowest}})^2 + (b^*_{\text{highest}} - b^*_{\text{lowest}})^2)}$.

[0064] Substrate

[0065] The substrate 110 may include an inorganic oxide material and may include an amorphous substrate, a crystalline substrate or a combination thereof. In one or more embodiments, the substrate exhibits a refractive index in the range from about 1.45 to about 1.55, e.g., 1.45, 1.46, 1.47, 1.48, 1.49, 1.50, 1.51, 1.52, 1.53, 1.54, 1.55, and all refractive indices therebetween.

[0066] Suitable substrates 110 may exhibit an elastic modulus (or Young's modulus) in the range from about 30 GPa to about 120 GPa. In some instances, the elastic modulus of the substrate may be in the range from about 30 GPa to about 110 GPa, from about 30 GPa to about 100 GPa, from about 30 GPa to about 90 GPa, from about 30 GPa to about 80 GPa, from about 30 GPa to about 70 GPa, from about 40 GPa to about 120 GPa, from about 50 GPa to about 120 GPa, from about 60 GPa to about 120 GPa, from about 70 GPa to about 120 GPa, and all ranges and sub-ranges therebetween. The Young's modulus values for the substrate itself as recited in

this disclosure refer to values as measured by a resonant ultrasonic spectroscopy technique of the general type set forth in ASTM E2001-13, titled “Standard Guide for Resonant Ultrasound Spectroscopy for Defect Detection in Both Metallic and Non-metallic Parts.”

[0067] In one or more embodiments, the amorphous substrate may include glass, which may be strengthened or non-strengthened. Examples of suitable glass include soda lime glass, alkali aluminosilicate glass, alkali containing borosilicate glass and alkali aluminoborosilicate glass. In some variants, the glass may be free of lithia. In one or more alternative embodiments, the substrate 110 may include crystalline substrates for example glass-ceramic, or ceramic, substrates (which may be strengthened or non-strengthened) or may include a single crystal structure, for example sapphire. In one or more specific embodiments, the substrate 110 includes an amorphous base (e.g., glass) and a crystalline cladding (e.g., sapphire layer, a polycrystalline alumina layer and/or or a spinel (MgAl_2O_4) layer).

[0068] The substrate 110 may be substantially planar or sheet-like, although other embodiments may utilize a curved or otherwise shaped or sculpted substrate. The substrate 110 may be substantially optically clear, transparent and free from light scattering. In such embodiments, the substrate may exhibit an average light transmission over the optical wavelength regime of about 85% or greater, about 86% or greater, about 87% or greater, about 88% or greater, about 89% or greater, about 90% or greater, about 91% or greater or about 92% or greater. In one or more alternative embodiments, the substrate 110 may be opaque or exhibit an average light transmission over the optical wavelength regime of less than about 10%, less than about 9%, less than about 8%, less than about 7%, less than about 6%, less than about 5%, less than about 4%, less than about 3%, less than about 2%, less than about 1%, or less than about 0%. In some embodiments, these light reflectance and transmittance values may be a total reflectance or total transmittance (taking into account reflectance or transmittance on both major surfaces of the substrate) or may be observed on a single side of the substrate (i.e., on the anti-reflective surface 122 only, without taking into account the opposite surface). Unless otherwise specified, the average reflectance or transmittance is measured at an incident illumination angle of 0 degrees (however, such measurements may be provided at incident illumination angles of 45 degrees or 60 degrees). The substrate 110 may optionally exhibit a color, for example white, black, red, blue, green, yellow, orange, etc.

[0069] Additionally or alternatively, the physical thickness of the substrate 110 may vary along one or more of its dimensions for aesthetic and/or functional reasons. For example, the edges of the substrate 110 may be thicker as compared to more central regions of the substrate 110. The length, width and physical thickness dimensions of the substrate 110 may also vary according to the application or use of the article 100.

[0070] The substrate 110 may be provided using a variety of different processes. For instance, where the substrate 110 includes an amorphous substrate for example glass, various forming methods can include float glass processes, rolling processes, updraw processes, and down-draw processes, for example fusion draw and slot draw.

[0071] Once formed, a substrate 110 may be strengthened to form a strengthened substrate. As used herein, the term "strengthened substrate" may refer to a substrate that has been chemically strengthened, for example through ion-exchange of larger ions for smaller ions in the surface of the substrate. However, other strengthening methods known in the art, for example thermal tempering, or utilizing a mismatch of the coefficient of thermal expansion between portions of the substrate to create compressive stress and central tension regions, may be utilized to form strengthened substrates.

[0072] Where the substrate is chemically strengthened by an ion exchange process, the ions in the surface layer of the substrate are replaced by – or exchanged with – larger ions having the same valence or oxidation state. Ion exchange processes are typically carried out by immersing a substrate in a molten salt bath containing the larger ions to be exchanged with the smaller ions in the substrate. It will be appreciated by those skilled in the art that parameters for the ion exchange process, including, but not limited to, bath composition and temperature, immersion time, the number of immersions of the substrate in a salt bath (or baths), use of multiple salt baths, additional steps for example annealing, washing, and the like, are generally determined by the composition of the substrate and the desired compressive stress (CS), depth of compressive stress (CS) layer (or depth of layer) of the substrate that result from the strengthening operation. By way of example, ion exchange of alkali metal-containing glass substrates may be achieved by immersion in at least one molten bath containing a salt for example, but not limited to, nitrates, sulfates, and chlorides of the larger alkali metal ion. The temperature of the molten salt bath typically is in a range from about 380°C up to about 450°C, while immersion times range from

about 15 minutes up to about 40 hours. However, temperatures and immersion times different from those described above may also be used.

[0073] In addition, non-limiting examples of ion exchange processes in which glass substrates are immersed in multiple ion exchange baths, with washing and/or annealing steps between immersions, are described in U.S. Patent Application No. 12/500,650, filed July 10, 2009, by Douglas C. Allan et al., entitled “Glass with Compressive Surface for Consumer Applications”, claiming priority from U.S. Provisional Patent Application No. 61/079,995, filed July 11, 2008, in which glass substrates are strengthened by immersion in multiple, successive, ion exchange treatments in salt baths of different concentrations; and U.S. Patent 8,312,739, by Christopher M. Lee et al., issued on November 20, 2012, and entitled “Dual Stage Ion Exchange for Chemical Strengthening of Glass,” claiming priority from U.S. Provisional Patent Application No. 61/084,398, filed July 29, 2008, in which glass substrates are strengthened by ion exchange in a first bath diluted with an effluent ion, followed by immersion in a second bath having a smaller concentration of the effluent ion than the first bath. The contents of U.S. Patent Application No. 12/500,650 and U.S. Patent No. 8,312,739 are incorporated herein by reference in their entirety.

[0074] The degree of chemical strengthening achieved by ion exchange may be quantified based on the parameters of central tension (CT), peak CS, depth of compression (DOC, which is the point along the thickness wherein compression changes to tension), and depth of ion layer (DOL). Peak CS, which is a maximum observed compressive stress, may be measured near the surface of the substrate 110 or within the strengthened glass at various depths. A peak CS value may include the measured CS at the surface (CS_s) of the strengthened substrate. In other embodiments, the peak CS is measured below the surface of the strengthened substrate. Compressive stress (including surface CS) is measured by surface stress meter (FSM) using commercially available instruments such as the FSM-6000, manufactured by Orihara Industrial Co., Ltd. (Japan). Surface stress measurements rely upon the accurate measurement of the stress optical coefficient (SOC), which is related to the birefringence of the glass. SOC in turn is measured according to Procedure C (Glass Disc Method) described in ASTM standard C770-16, entitled “Standard Test Method for Measurement of Glass Stress-Optical Coefficient,” the contents of which are incorporated herein by reference in their entirety. As used herein, DOC means the depth at which the stress in the chemically strengthened alkali aluminosilicate glass article described herein changes from compressive to tensile. DOC may be measured by FSM or

a scattered light polariscope (SCALP) depending on the ion exchange treatment. Where the stress in the glass article is generated by exchanging potassium ions into the glass article, FSM is used to measure DOC. Where the stress is generated by exchanging sodium ions into the glass article, SCALP is used to measure DOC. Where the stress in the glass article is generated by exchanging both potassium and sodium ions into the glass, the DOC is measured by SCALP, since it is believed the exchange depth of sodium indicates the DOC and the exchange depth of potassium ions indicates a change in the magnitude of the compressive stress (but not the change in stress from compressive to tensile); the exchange depth of potassium ions in such glass articles is measured by FSM. Maximum CT values are measured using a scattered light polariscope (SCALP) technique known in the art. Refracted near-field (RNF) method or SCALP may be used to measure (graph, depict visually, or otherwise map out) the complete stress profile. When the RNF method is utilized to measure the stress profile, the maximum CT value provided by SCALP is utilized in the RNF method. In particular, the stress profile measured by RNF is force balanced and calibrated to the maximum CT value provided by a SCALP measurement. The RNF method is described in U.S. Patent No. 8,854,623, entitled “Systems and methods for measuring a profile characteristic of a glass sample”, which is incorporated herein by reference in its entirety. In particular, the RNF method includes placing the glass article adjacent to a reference block, generating a polarization-switched light beam that is switched between orthogonal polarizations at a rate of from 1 Hz to 50 Hz, measuring an amount of power in the polarization-switched light beam and generating a polarization-switched reference signal, wherein the measured amounts of power in each of the orthogonal polarizations are within 50% of each other. The method further includes transmitting the polarization-switched light beam through the glass sample and reference block for different depths into the glass sample, then relaying the transmitted polarization-switched light beam to a signal photodetector using a relay optical system, with the signal photodetector generating a polarization-switched detector signal. The method also includes dividing the detector signal by the reference signal to form a normalized detector signal and determining the profile characteristic of the glass sample from the normalized detector signal.

[0075] In some embodiments, a strengthened substrate 110 can have a peak CS of 250 MPa or greater, 300 MPa or greater, 400 MPa or greater, 450 MPa or greater, 500 MPa or greater, 550 MPa or greater, 600 MPa or greater, 650 MPa or greater, 700 MPa or greater, 750 MPa or

greater, or 800 MPa or greater. The strengthened substrate may have a DOC of 10 μm or greater, 15 μm or greater, 20 μm or greater (e.g., 25 μm , 30 μm , 35 μm , 40 μm , 45 μm , 50 μm or greater) and/or a CT of 10 MPa or greater, 20 MPa or greater, 30 MPa or greater, 40 MPa or greater (e.g., 42 MPa, 45 MPa, or 50 MPa or greater) but less than 100 MPa (e.g., 95, 90, 85, 80, 75, 70, 65, 60, 55 MPa or less). In one or more specific embodiments, the strengthened substrate has one or more of the following: a peak CS greater than 500 MPa, a DOC greater than 15 μm , and a CT greater than 18 MPa.

[0076] Example glasses that may be used in the substrate may include alkali aluminosilicate glass compositions or alkali aluminoborosilicate glass compositions, though other glass compositions are contemplated. Such glass compositions are capable of being chemically strengthened by an ion exchange process. One example glass composition comprises SiO_2 , B_2O_3 and Na_2O , where $(\text{SiO}_2 + \text{B}_2\text{O}_3) \geq 66$ mol. %, and $\text{Na}_2\text{O} \geq 9$ mol. %. In some embodiments, the glass composition includes about 6 wt.% aluminum oxide or more. In some embodiments, the substrate includes a glass composition with one or more alkaline earth oxides, such that a content of alkaline earth oxides is about 5 wt.% or more. Suitable glass compositions, in some embodiments, further comprise at least one of K_2O , MgO , or CaO . In some embodiments, the glass compositions used in the substrate can comprise 61-75 mol.% SiO_2 ; 7-15 mol.% Al_2O_3 ; 0-12 mol.% B_2O_3 ; 9-21 mol.% Na_2O ; 0-4 mol.% K_2O ; 0-7 mol.% MgO ; and 0-3 mol.% CaO .

[0077] A further example glass composition suitable for the substrate comprises: 60-70 mol.% SiO_2 ; 6-14 mol.% Al_2O_3 ; 0-15 mol.% B_2O_3 ; 0-15 mol.% Li_2O ; 0-20 mol.% Na_2O ; 0-10 mol.% K_2O ; 0-8 mol.% MgO ; 0-10 mol.% CaO ; 0-5 mol.% ZrO_2 ; 0-1 mol.% SnO_2 ; 0-1 mol.% CeO_2 ; less than 50 ppm As_2O_3 ; and less than 50 ppm Sb_2O_3 ; where $12 \text{ mol.} \% \leq (\text{Li}_2\text{O} + \text{Na}_2\text{O} + \text{K}_2\text{O}) \leq 20 \text{ mol.} \%$ and $0 \text{ mol.} \% \leq (\text{MgO} + \text{CaO}) \leq 10 \text{ mol.} \%$.

[0078] A still further example glass composition suitable for the substrate comprises: 63.5-66.5 mol.% SiO_2 ; 8-12 mol.% Al_2O_3 ; 0-3 mol.% B_2O_3 ; 0-5 mol.% Li_2O ; 8-18 mol.% Na_2O ; 0-5 mol.% K_2O ; 1-7 mol.% MgO ; 0-2.5 mol.% CaO ; 0-3 mol.% ZrO_2 ; 0.05-0.25 mol.% SnO_2 ; 0.05-0.5 mol.% CeO_2 ; less than 50 ppm As_2O_3 ; and less than 50 ppm Sb_2O_3 ; where $14 \text{ mol.} \% \leq (\text{Li}_2\text{O} + \text{Na}_2\text{O} + \text{K}_2\text{O}) \leq 18 \text{ mol.} \%$ and $2 \text{ mol.} \% \leq (\text{MgO} + \text{CaO}) \leq 7 \text{ mol.} \%$.

[0079] In some embodiments, an alkali aluminosilicate glass composition suitable for the substrate 110 comprises alumina, at least one alkali metal and, in some embodiments, greater

than 50 mol.% SiO₂, in other embodiments 58 mol.% SiO₂ or more, and in still other embodiments 60 mol.% SiO₂ or more, wherein the ratio (Al₂O₃ + B₂O₃)/Σmodifiers (i.e., sum of modifiers) is greater than 1, wherein the ratio the components are expressed in mol.% and the modifiers are alkali metal oxides. This glass composition, in particular embodiments, comprises: 58-72 mol.% SiO₂; 9-17 mol.% Al₂O₃; 2-12 mol.% B₂O₃; 8-16 mol.% Na₂O; and 0-4 mol.% K₂O, wherein the ratio (Al₂O₃ + B₂O₃)/Σmodifiers (i.e., sum of modifiers) is greater than 1.

[0080] In some embodiments, the substrate 110 may include an alkali aluminosilicate glass composition comprising: 64-68 mol.% SiO₂; 12-16 mol.% Na₂O; 8-12 mol.% Al₂O₃; 0-3 mol.% B₂O₃; 2-5 mol.% K₂O; 4-6 mol.% MgO; and 0-5 mol.% CaO, wherein: 66 mol.% ≤ SiO₂ + B₂O₃ + CaO ≤ 69 mol.%; Na₂O + K₂O + B₂O₃ + MgO + CaO + SrO > 10 mol.%; 5 mol.% ≤ MgO + CaO + SrO ≤ 8 mol.%; (Na₂O + B₂O₃) – Al₂O₃ ≤ 2 mol.%; 2 mol.% ≤ Na₂O – Al₂O₃ ≤ 6 mol.%; and 4 mol.% ≤ (Na₂O + K₂O) – Al₂O₃ ≤ 10 mol.%.

[0081] In some embodiments, the substrate 110 may comprise an alkali aluminosilicate glass composition comprising: 2 mol% or more of Al₂O₃ and/or ZrO₂, or 4 mol% or more of Al₂O₃ and/or ZrO₂.

[0082] Where the substrate 110 includes a crystalline substrate, the substrate may include a single crystal, which may include Al₂O₃. Such single crystal substrates are referred to as sapphire. Other suitable materials for a crystalline substrate include polycrystalline alumina layer and/or spinel (MgAl₂O₄).

[0083] Optionally, the crystalline substrate 110 may include a glass-ceramic substrate, which may be strengthened or non-strengthened. Examples of suitable glass-ceramics may include Li₂O-Al₂O₃-SiO₂ system (i.e. LAS-System) glass-ceramics, MgO-Al₂O₃-SiO₂ system (i.e. MAS-System) glass-ceramics, and/or glass-ceramics that include a predominant crystal phase including β-quartz solid solution, β-spodumene ss, cordierite, and lithium disilicate. The glass-ceramic substrates may be strengthened using the chemical strengthening processes disclosed herein. In one or more embodiments, MAS-System glass-ceramic substrates may be strengthened in Li₂SO₄ molten salt, whereby an exchange of 2Li⁺ for Mg²⁺ can occur.

[0084] The substrate 110, according to one or more embodiments, can have a physical thickness ranging from about 50 μm to about 5 mm. Example substrate 110 physical thicknesses range from about 50 μm to about 500 μm (e.g., 50, 100, 200, 300, 400 or 500 μm). Further

example substrate 110 physical thicknesses range from about 500 μm to about 1000 μm (e.g., 500, 600, 700, 800, 900 or 1000 μm). The substrate 110 may have a physical thickness greater than about 1 mm (e.g., about 2, 3, 4, or 5 mm). In one or more specific embodiments, the substrate 110 may have a physical thickness of 2 mm or less or less than 1 mm. The substrate 110 may be acid polished or otherwise treated to remove or reduce the effect of surface flaws.

[0085] Anti-Reflective Coating

[0086] As shown in FIG. 1, the anti-reflective coating 120 of the article 100 may include a plurality of layers 120A, 120B, 120C (also referred herein as “optical films”). In some embodiments, one or more layers may be disposed on the opposite side of the substrate 110 from the anti-reflective coating 120 (i.e., on major surface 114)(not shown). In some embodiments of the article 100, layer 120C, as shown in FIG. 1, can serve as a capping layer (e.g., capping layer 131 as shown in FIGS. 2A, 2B and 2C, and described in the sections below).

[0087] The physical thickness of the anti-reflective coating 120 may be in the range from about 50 nm to less than 500 nm. In some instances, the physical thickness of the anti-reflective coating 120 may be in the range from about 10 nm to less than 500 nm, from about 50 nm to less than 500 nm, from about 75 nm to less than 500 nm, from about 100 nm to less than 500 nm, from about 125 nm to less than 500 nm, from about 150 nm to less than 500 nm, from about 175 nm to less than 500 nm, from about 200 nm to less than 500 nm, from about 225 nm to less than 500 nm, from about 250 nm to less than 500 nm, from about 300 nm to less than 500 nm, from about 350 nm to less than 500 nm, from about 400 nm to less than 500 nm, from about 450 nm to less than 500 nm, from about 200 nm to about 450 nm, and all ranges and sub-ranges therebetween. For example, the physical thickness of the anti-reflective coating 120 may be from 10 nm to 490 nm, or from 10 nm to 480 nm, or from 10 nm to 475 nm, or from 10 nm to 460 nm, or from 10 nm to 450 nm, or from 10 nm to 450 nm, or from 10 nm to 430 nm, or from 10 nm to 425 nm, or from 10 nm to 420 nm, or from 10 nm to 410 nm, or from 10 nm to 400 nm, or from 10 nm to 350 nm, or from 10 nm to 300 nm, or from 10 nm to 250 nm, or from 10 nm to 225 nm, or from 10 nm to 200 nm, or from 15 nm to 490 nm, or from 20 nm to 490 nm, or from 25 nm to 490 nm, or from 30 nm to 490 nm, or from 35 nm to 490 nm, or from 40 nm to 490 nm, or from 45 nm to 490 nm, or from 50 nm to 490 nm, or from 55 nm to 490 nm, or from 60 nm to 490 nm, or from 65 nm to 490 nm, or from 70 nm to 490 nm, or from 75 nm to 490 nm, or from 80 nm to 490 nm, or from 85 nm to 490 nm, or from 90 nm to 490 nm, or from 95 nm to 490 nm,

or from 100 nm to 490 nm, or from 10 nm to 485 nm, or from 15 nm to 480 nm, or from 20 nm to 475 nm, or from 25 nm to 460 nm, or from 30 nm to 450 nm, or from 35 nm to 440 nm, or from 40 nm to 430 nm, or from 50 nm to 425 nm, or from 55 nm to 420 nm, or from 60 nm to 410 nm, or from 70 nm to 400 nm, or from 75 nm to 400 nm, or from 80 nm to 390 nm, or from 90 nm to 380 nm, or from 100 nm to 375 nm, or from 110 nm to 370 nm, or from 120 nm to 360 nm, or from 125 nm to 350 nm, or from 130 nm to 325 nm, or from 140 nm to 320 nm, or from 150 nm to 310 nm, or from 160 nm to 300 nm, or from 170 nm to 300 nm, or from 175 nm to 300 nm, or from 180 nm to 290 nm, or from 190 nm to 280 nm, or from 200 nm to 275 nm.

[0088] According to some implementations, the physical thickness of any one or more of the optical film(s) 130B of the anti-reflective coating 120 ranges from about 50 nm to about 3000 nm (see, e.g., FIG. 2C and corresponding description below). In some instances, the physical thickness of any one or more of the optical film(s) 130B of the anti-reflective coating 120 may be in the range from about 50 nm to less than about 3000 nm, from about 100 nm to less than about 3000 nm, from about 200 nm to less than about 3000 nm, from about 300 nm to less than about 3000 nm, from about 400 nm to less than about 3000 nm, from about 500 nm to less than about 3000 nm, and all ranges and sub-ranges therebetween.

[0089] According to some embodiments, any one or more of the layers 130B or optical film(s) 130B of the anti-reflective coating 120 can be characterized by a surface roughness (R_a) of less than 3.0, less than 2.5, less than 2.0, or less than 1.5, and all surface roughness (R_a) values therebetween. Unless otherwise noted, the surface roughness (R_a) of the optical film(s) 130B of the anti-reflective coating 120 is as measured upon deposition of the film 130B onto a test glass substrate.

[0090] In one or more embodiments, as shown in FIGS. 2A and 2B, the anti-reflective coating 120 of the article 100 may include a period 130 comprising two or more layers. Further, the anti-reflective coating 120 can form an anti-reflective surface 122, as also shown in FIGS. 2A and 2B. In one or more embodiments, the two or more layers may be characterized as having different refractive indices from each another. In some embodiments, the period 130 includes a first low RI layer 130A and a second high RI layer 130B. The difference in the refractive index of the first low RI layer 130A and the second high RI layer 130B may be about 0.01 or greater, 0.05 or greater, 0.1 or greater or even 0.2 or greater. In some implementations, the refractive index of the low RI layer(s) 130A is within the refractive index of the substrate 110 such that the

refractive index of the low RI layer(s) 130A is less than about 1.8, and the high RI layer(s) 130B have a refractive index that is greater than 1.8.

[0091] As shown in FIG. 2A, the anti-reflective coating 120 may include a plurality of periods (130). A single period includes a first low RI layer 130A and a second high RI layer 130B, such that when a plurality of periods are provided, the first low RI layer 130A (designated for illustration as “L”) and the second high RI layer 130B (designated for illustration as “H”) alternate in the following sequence of layers: L/H/L/H or H/L/H/L, such that the first low RI layer and the second high RI layer appear to alternate along the physical thickness of the anti-reflective coating 120. In the example in FIG. 2A, the anti-reflective coating 120 includes three periods 130 such that there are three pairs of low RI and high RI layers 130A and 130B, respectively. In the example in FIG. 2B, the anti-reflective coating 120 includes two periods 130 such that there are two pairs of low RI and high RI layers 130A and 130B, respectively. In some embodiments, the anti-reflective coating 120 may include up to 25 periods. For example, the anti-reflective coating 120 may include from about 2 to about 20 periods, from about 2 to about 15 periods, from about 2 to about 10 periods, from about 2 to about 12 periods, from about 3 to about 8 periods, from about 3 to about 6 periods.

[0092] In the embodiments of the article 100 shown in FIGS. 2A and 2B, the anti-reflective coating 120 may include an additional capping layer 131, which may include a lower refractive index material than the second high RI layer 130B. In some implementations, the refractive index of the capping layer 131 is the same or substantially the same as the refractive index of the low RI layers 130A.

[0093] Referring now to FIG. 2C, an optical article 100 is provided that includes: an inorganic oxide substrate 110 comprising opposing major surfaces (e.g., primary surfaces 112 and 114, shown in FIG. 1); and an optical film structure 120 disposed on a first major surface of the inorganic oxide substrate. In some embodiments, the optical film structure 120 can form an anti-reflective surface 122, as also shown in FIG. 2C. Further, the optical film structure 120 of the optical article 100 depicted in FIG. 2C includes an optical film 130A comprising a physical thickness from about 50 nm to about 3000 nm. As shown in FIG. 2A, the optical film structure 120 includes a single optical film 130B; however, in some embodiments of the optical article 100 exemplified by FIG. 2C but not otherwise depicted in schematic form, intervening layers may be present between the optical film 130B and the substrate 110 and/or the capping layer 131 (if

present). Further, in these implementations, the optical film 130B is made of a silicon-containing nitride (e.g., SiN_x) or a silicon-containing oxynitride (e.g., SiO_xN_y). The optical film 130B exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate (e.g., as comparable to inorganic oxide substrate 110), the test optical film having the same composition as the optical film 130B. Further, the optical film 130B, according to some embodiments, exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm. Further, in some implementations of the optical article 100 depicted in FIG. 2C, the optical film 130B can be a high RI layer 130B, as described in other sections of this disclosure.

[0094] As used herein, the terms “low RI” and “high RI” refer to the relative values for the RI of each layer relative to the RI of another layer within the anti-reflective coating 120 (e.g., low RI < high RI). In one or more embodiments, the term “low RI” when used with the first low RI layer 130A or with the capping layer 131, includes a range from about 1.3 to about 1.7. In one or more embodiments, the term “high RI” when used with the high RI layer 130B, includes a range of refractive indices (n) from about 1.6 to about 2.5. In one or more embodiments, the term “high RI” when used with the high RI layer 130B, includes a range of refractive indices (n) from about 1.8 to about 2.5. In some instances, the ranges for low RI and high RI may overlap; however, in most instances, the layers of the anti-reflective coating 120 have the general relationship regarding RI of: low RI < high RI.

[0095] According to another implementation (e.g., as shown in FIGS. 2A, 2B and 2C), any one or more of the optical film(s) 130B of the anti-reflective coating 120 can have a refractive index that is greater than 1.8 as measured at a wavelength of 550 nm. In some implementations, the refractive index of the optical film(s) 130B is greater than 1.8, greater than 1.9, greater than 2.0, or even greater than 2.1 in some instances, as measured at a wavelength of 550 nm. In some embodiments, any one or more of the optical film(s) 130B of the anti-reflective coating 120 can be characterized by an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm, or a wavelength of 300 nm. According to some embodiments, the optical film(s) 130B can be characterized by an optical extinction coefficient (k) of less than 1×10^{-2} , of less than $5 \times$

10^{-3} , of less than 1×10^{-3} , of less than 5×10^{-4} , of less than 1×10^{-4} , or of less than 5×10^{-5} , as measured at a wavelength of 400 nm or 300 nm.

[0096] Exemplary materials suitable for use in the anti-reflective coating 120 include: SiO_2 , Al_2O_3 , GeO_2 , SiO , AlO_xN_y , AlN , oxygen-doped SiN_x , SiN_x , SiO_xN_y , $\text{Si}_u\text{Al}_v\text{O}_x\text{N}_y$, TiO_2 , ZrO_2 , TiN , MgO , HfO_2 , Y_2O_3 , ZrO_2 , diamond-like carbon, and MgAl_2O_4 .

[0097] Some examples of suitable materials for use in the low RI layer(s) 130A include SiO_2 , Al_2O_3 , GeO_2 , SiO , AlO_xN_y , SiO_xN_y , $\text{Si}_u\text{Al}_v\text{O}_x\text{N}_y$, MgO , and MgAl_2O_4 . The nitrogen content of the materials for use in the first low RI layer 130A (i.e., the layer 130A in contact with the substrate 110) may be minimized (e.g., in materials for example Al_2O_3 and MgAl_2O_4). In some embodiments, the low RI layer(s) 130A and a capping layer 131, if present, in the anti-reflective coating 120 can comprise one or more of a silicon-containing oxide (e.g., silicon dioxide), a silicon-containing nitride (e.g., an oxide-doped silicon nitride, silicon nitride, etc.), and a silicon-containing oxynitride (e.g., silicon oxynitride). In some embodiments of the article 100, the low RI layer(s) 130A and the capping layer 131 comprise a silicon-containing oxide, e.g., SiO_2 .

[0098] Some examples of suitable materials for use in the high RI layer(s) 130B include $\text{Si}_u\text{Al}_v\text{O}_x\text{N}_y$, AlN , oxygen-doped SiN_x , SiN_x , Si_3N_4 , AlO_xN_y , SiO_xN_y , HfO_2 , TiO_2 , ZrO_2 , Y_2O_3 , ZrO_2 , Al_2O_3 , and diamond-like carbon. The oxygen content of the materials for the high RI layer(s) 130B may be minimized, especially in SiN_x or AlN_x materials. The foregoing materials may be hydrogenated up to about 30% by weight. In some embodiments, the high RI layer(s) 130B in the anti-reflective coating 120 can comprise one or more of a silicon-containing oxide (e.g., silicon dioxide), a silicon-containing nitride (e.g., an oxide-doped silicon nitride, silicon nitride, etc.), and a silicon-containing oxynitride (e.g., silicon oxynitride). In some embodiments of the article 100, the high RI layer(s) 130B comprise a silicon-containing nitride, e.g., Si_3N_4 . Where a material having a medium refractive index is desired between a high RI and a low RI, some embodiments may utilize AlN and/or SiO_xN_y . The hardness of the high RI layer may be characterized specifically. In some embodiments, the maximum hardness of the high RI layer(s) 130B, as measured by the Berkovich Indenter Hardness Test over an indentation depth from about 100 nm to about 500 nm (i.e., as on a hardness test stack with a 2 micron thick layer of the material of the layer 130B disposed on a substrate 110), may be about 18 GPa or greater, about 20 GPa or greater, about 22 GPa or greater, about 24 GPa or greater, about 26 GPa or greater, and all values therebetween.

[0099] In one or more embodiments at least one of the layers of the anti-reflective coating 120 of the article 100 may include a specific optical thickness range. As used herein, the term “optical thickness” is determined by $(n \cdot d)$, where “n” refers to the RI of the sub-layer and “d” refers to the physical thickness of the layer. In one or more embodiments, at least one of the layers of the anti-reflective coating 120 may include an optical thickness in the range from about 2 nm to about 200 nm, from about 10 nm to about 100 nm, or from about 15 nm to about 100 nm. In some embodiments, all of the layers in the anti-reflective coating 120 may each have an optical thickness in the range from about 2 nm to about 200 nm, from about 10 nm to about 100 nm, or from about 15 nm to about 100 nm. In some cases, at least one layer of the anti-reflective coating 120 has an optical thickness of about 50 nm or greater. In some cases, each of the low RI layers 130A have an optical thickness in the range from about 2 nm to about 200 nm, from about 10 nm to about 100 nm, or from about 15 nm to about 100 nm. In other cases, each of the high RI layers 130B have an optical thickness in the range from about 2 nm to about 200 nm, from about 10 nm to about 100 nm, or from about 15 nm to about 100 nm. In some embodiments, each of the high RI layers 130B have an optical thickness in the range from about 2 nm to about 500 nm, or from about 10 nm to about 490 nm, or from about 15 nm to about 480 nm, or from about 25 nm to about 475 nm, or from about 25 nm to about 470 nm, or from about 30 nm to about 465 nm, or from about 35 nm to about 460 nm, or from about 40 nm to about 455 nm, or from about 45 nm to about 450 nm, and any and all sub-ranges between these values. In some embodiments, the capping layer 131 (see FIGS. 2A, 2B and 3), or the outermost low RI layer 130A for configurations without a capping layer 131, has a physical thickness of less than about 100 nm, less than about 90 nm, less than about 85 nm, or less than 80 nm.

[00100] As noted earlier, embodiments of the article 100 are configured such that the physical thickness of one or more of the layers of the anti-reflective coating 120 are minimized. In one or more embodiments, the physical thickness of the high RI layer(s) 130B and/or the low RI layer(s) 130A are minimized such that they total less than 500 nm. In one or more embodiments, the combined physical thickness of the high RI layer(s) 130B, the low RI layer(s) 130A and any capping layer 131 is less than 500 nm, less than 490 nm, less than 480 nm, less than 475 nm, less than 470 nm, less than 460 nm, less than about 450 nm, less than 440 nm, less than 430 nm, less than 425 nm, less than 420 nm, less than 410 nm, less than about 400 nm, less than about 350 nm, less than about 300 nm, less than about 250 nm, or less than about 200 nm, and all total

thickness values below 500 nm and above 10 nm. For example, the combined physical thickness of the high RI layer(s) 130B, the low RI layer(s) 130A and any capping layer 131 may be from 10 nm to 490 nm, or from 10 nm to 480 nm, or from 10 nm to 475 nm, or from 10 nm to 460 nm, or from 10 nm to 450 nm, or from 10 nm to 450 nm, or from 10 nm to 430 nm, or from 10 nm to 425 nm, or from 10 nm to 420 nm, or from 10 nm to 410 nm, or from 10 nm to 400 nm, or from 10 nm to 350 nm, or from 10 nm to 300 nm, or from 10 nm to 250 nm, or from 10 nm to 225 nm, or from 10 nm to 200 nm, or from 15 nm to 490 nm, or from 20 nm to 490 nm, or from 25 nm to 490 nm, or from 30 nm to 490 nm, or from 35 nm to 490 nm, or from 40 nm to 490 nm, or from 45 nm to 490 nm, or from 50 nm to 490 nm, or from 55 nm to 490 nm, or from 60 nm to 490 nm, or from 65 nm to 490 nm, or from 70 nm to 490 nm, or from 75 nm to 490 nm, or from 80 nm to 490 nm, or from 85 nm to 490 nm, or from 90 nm to 490 nm, or from 95 nm to 490 nm, or from 100 nm to 490 nm, or from 10 nm to 485 nm, or from 15 nm to 480 nm, or from 20 nm to 475 nm, or from 25 nm to 460 nm, or from 30 nm to 450 nm, or from 35 nm to 440 nm, or from 40 nm to 430 nm, or from 50 nm to 425 nm, or from 55 nm to 420 nm, or from 60 nm to 410 nm, or from 70 nm to 400 nm, or from 75 nm to 400 nm, or from 80 nm to 390 nm, or from 90 nm to 380 nm, or from 100 nm to 375 nm, or from 110 nm to 370 nm, or from 120 nm to 360 nm, or from 125 nm to 350 nm, or from 130 nm to 325 nm, or from 140 nm to 320 nm, or from 150 nm to 310 nm, or from 160 nm to 300 nm, or from 170 nm to 300 nm, or from 175 nm to 300 nm, or from 180 nm to 290 nm, or from 190 nm to 280 nm, or from 200 nm to 275 nm.

[00101] In one or more embodiments, the combined physical thickness of the high RI layer(s) 130B may be characterized. For example, in some embodiments, the combined physical thickness of the high RI layer(s) 130B may be about 90 nm or greater, about 100 nm or greater, about 150 nm or greater, about 200 nm or greater, about 250 nm or greater, or about 300 nm or greater, but less than 500 nm. The combined physical thickness is the calculated combination of the physical thicknesses of the individual high RI layer(s) 130B in the anti-reflective coating 120, even when there are intervening low RI layer(s) 130A or other layer(s). In some embodiments, the combined physical thickness of the high RI layer(s) 130B, which may also comprise a high-hardness material (e.g., a nitride or an oxynitride), may be greater than 30% of the total physical thickness of the anti-reflective coating (or, alternatively referred to in the context of volume). For example, the combined physical thickness (or volume) of the high RI layer(s) 130B may be about 30% or greater, about 35% or greater, about 40% or greater, about

45% or greater, about 50% or greater, about 55% or greater, or even about 60% or greater, of the total physical thickness (or volume) of the anti-reflective coating 120.

[00102] In some embodiments, the anti-reflective coating 120 exhibits a photopic average light reflectance of 1% or less, 0.9% or less, 0.8% or less, 0.7% or less, 0.6% or less, 0.5% or less, 0.4% or less, 0.3% or less, 0.25% or less, or 0.2% or less, over the optical wavelength regime, when measured at the anti-reflective surface 122 (e.g., when removing the reflections from an uncoated back surface (e.g., 114 in FIG. 1) of the article 100, for example through using index-matching oils on the back surface coupled to an absorber, or other known methods). In some instances, the anti-reflective coating 120 may exhibit such average light reflectance over other wavelength ranges for example from about 450 nm to about 650 nm, from about 420 nm to about 680 nm, from about 420 nm to about 700 nm, from about 420 nm to about 740 nm, from about 420 nm to about 850 nm, or from about 420 nm to about 950 nm. In some embodiments, the anti-reflective surface 122 exhibits a photopic average light transmission of about 90% or greater, 92% or greater, 94% or greater, 96% or greater, or 98% or greater, over the optical wavelength regime. Unless otherwise specified, the average reflectance or transmittance is measured at an incident illumination angle of 0 degrees (however, such measurements may be provided at incident illumination angles of 45 degrees or 60 degrees).

[00103] The article 100 may include one or more additional coatings 140 disposed on the anti-reflective coating 120, as shown in FIG. 3. In some embodiments, the additional coating 140 is also an anti-reflective coating, e.g., as having a single-side photopic average reflectance of less than 1%. It should also be understood that the one or more additional coatings 140 depicted in FIG. 3 can also be employed in a similar fashion over the anti-reflective coating 120, optical film structure 120 and/or capping layer 131 employed in embodiments of the articles 100 shown in FIGS. 2A-2C.

[00104] In one or more embodiments, the additional coating 140 may also include an easy-to-clean coating. An example of a suitable easy-to-clean coating is described in U.S. Patent Application No. 13/690,904, entitled "PROCESS FOR MAKING OF GLASS ARTICLES WITH OPTICAL AND EASY-TO-CLEAN COATINGS," filed on November 30, 2012, which is incorporated herein in its entirety by reference. The easy-to-clean coating may have a physical thickness in the range from about 5 nm to about 50 nm and may include known materials for example fluorinated silanes. In some embodiments, the easy-to-clean coating may have a

physical thickness in the range from about 1 nm to about 40 nm, from about 1 nm to about 30 nm, from about 1 nm to about 25 nm, from about 1 nm to about 20 nm, from about 1 nm to about 15 nm, from about 1 nm to about 10 nm, from about 5 nm to about 50 nm, from about 10 nm to about 50 nm, from about 15 nm to about 50 nm, from about 7 nm to about 20 nm, from about 7 nm to about 15 nm, from about 7 nm to about 12 nm or from about 7 nm to about 10 nm, and all ranges and sub-ranges therebetween.

[00105] The additional coating 140 may include a scratch resistant coating. Exemplary materials used in the scratch resistant coating may include an inorganic carbide, nitride, oxide, diamond-like material, or combination of these. Examples of suitable materials for the scratch resistant coating include metal oxides, metal nitrides, metal oxynitride, metal carbides, metal oxycarbides, and/or combinations thereof. Exemplary metals include B, Al, Si, Ti, V, Cr, Y, Zr, Nb, Mo, Sn, Hf, Ta and W. Specific examples of materials that may be utilized in the scratch resistant coating may include Al_2O_3 , AlN , AlO_xN_y , Si_3N_4 , SiO_xN_y , $\text{Si}_u\text{Al}_v\text{O}_x\text{N}_y$, diamond, diamond-like carbon, Si_xC_y , $\text{Si}_x\text{O}_y\text{C}_z$, ZrO_2 , TiO_xN_y and combinations thereof.

[00106] In some embodiments, the additional coating 140 includes a combination of easy-to-clean material and scratch resistant material. In one example, the combination includes an easy-to-clean material and diamond-like carbon. Such additional coatings 140 may have a physical thickness in the range from about 5 nm to about 20 nm. The constituents of the additional coating 140 may be provided in separate layers. For example, the diamond-like carbon material may be disposed as a first layer and the easy-to-clean material can be disposed as a second layer on the first layer of diamond-like carbon. The physical thicknesses of the first layer and the second layer may be in the ranges provided above for the additional coating. For example, the first layer of diamond-like carbon may have a physical thickness of about 1 nm to about 20 nm or from about 4 nm to about 15 nm (or more specifically about 10 nm) and the second layer of easy-to-clean may have a physical thickness of about 1 nm to about 10 nm (or more specifically about 6 nm). The diamond-like coating may include tetrahedral amorphous carbon (Ta-C), Ta-C:H, and/or a-C-H.

[00107] A further aspect of this disclosure pertains to a method for forming the articles 100 described herein (e.g., as shown in FIGS. 1-3). In some embodiments, the method includes providing a substrate having a major surface in a coating chamber, forming a vacuum in the coating chamber, forming a durable anti-reflective coating having a physical thickness of about

500 nm or less on the major surface, optionally forming an additional coating comprising at least one of an easy-to-clean coating or a scratch resistant coating, on the anti-reflective coating, and removing the substrate from the coating chamber. In one or more embodiments, the anti-reflective coating and the additional coating are formed in either the same coating chamber or without breaking vacuum in separate coating chambers.

[00108] According to another aspect of the disclosure, a method for forming articles 100 described herein, including an optical film 130B of an anti-reflective coating 120, is provided. The method includes: providing a substrate comprising opposing major surfaces within a sputtering chamber; sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride; and removing the optical film and the substrate from the chamber. In some implementations, the sputtering is conducted with a reactive sputtering process, an in-line sputtering process or a rotary metal-mode reactive sputtering process, each of which can be conducted with sputtering equipment, fixtures and targets suitable for the particular process, as understood by those of ordinary skill in the field of the disclosure.

[00109] In one or more embodiments, the method may include loading the substrate on carriers which are then used to move the substrate in and out of different coating chambers, under load lock conditions so that a vacuum is preserved as the substrate is moved.

[00110] The anti-reflective coating 120 (e.g., including layers 130A, 130B and 131) and/or the additional coating 140 may be formed using various deposition methods for example vacuum deposition techniques, for example, chemical vapor deposition (e.g., plasma enhanced chemical vapor deposition (PECVD), low-pressure chemical vapor deposition, atmospheric pressure chemical vapor deposition, and plasma-enhanced atmospheric pressure chemical vapor deposition), physical vapor deposition (e.g., reactive or nonreactive sputtering or laser ablation), thermal or e-beam evaporation and/or atomic layer deposition. Liquid-based methods may also be used for example spraying or slot coating. Where vacuum deposition is utilized, inline processes may be used to form the anti-reflective coating 120 and/or the additional coating 140 in one deposition run. In some instances, the vacuum deposition can be made by a linear PECVD source. In some implementations of the method, and articles 100 made according to the method, the anti-reflective coating 120 can be prepared using a sputtering process (e.g., a

reactive sputtering process), chemical vapor deposition (CVD) process, plasma-enhanced chemical vapor deposition process, or some combination of these processes. In one implementation, an anti-reflective coating 120 comprising low RI layer(s) 130A and high RI layer(s) 130B can be prepared according to a reactive sputtering process. According to some embodiments, the anti-reflective coating 120 (including low RI layer 130A, high RI layer 130B and capping layer 131) of the article 100 is fabricated using a metal-mode, reactive sputtering in a rotary drum coater. The reactive sputtering process conditions were defined through careful experimentation to achieve the desired combinations of hardness, refractive index, optical transparency, low color and controlled film stress.

[00111] In some implementations of the foregoing methods, the anti-reflective coating 120, including any of its optical film(s) 130B, can be formed with a sputtering process. The properties of these materials and films made in vapor deposition, in this case sputtering, depend on a number of process and geometric parameters. While the exact process settings are typically highly dependent on the specific details of an individual coating system, including such details as how the samples are held in fixtures, how different sections of the chamber are shielded from one another to minimize debris and defects, etc., the methods of the disclosure can be implemented to define ranges of process conditions and geometries that are useful or preferred across a range of different coating systems, in this case a range of sputtering systems. For example, throw distance is the physical distance between the sputtering target and the substrate, which can affect the arrival rate and plasma interactions with the film as it is being deposited (growing) on the substrate. This, in turn, can affect film morphology density, hardness, chemistry, and optical properties. Other geometric effects and process settings can also affect film properties through varying mechanisms. For example, the power applied to and the size of the sputtering target can affect the plasma energy and the energy of ions bombarding the sputtering target, which relates to the energy of atoms and/or molecular clusters that are sputtered off the target, which in turn affects their velocity, reactivity, and energy available to rearrange, both in transit between the target and substrate, and once they reach the substrate surface and are deposited. Cylindrical sputtering targets are used in both continuous in-line and rotary metal-mode sputter coating systems, and are typically quantified in terms of target length and power per unit length. In contrast, planar sputtering targets, though they can be used in all kinds of sputtering systems, are more typically used in box-type or lab-scale sputter coaters, and

are quantified in terms of target area and power per unit area. Chamber pressure can affect atomic collisions for sputtered atoms in transit between target and substrate, as well as the plasma energy, energy of arriving atoms, and film density through interaction of gases with the film as it forms on the substrate. Power frequency and pulsing also has an important influence on plasma energy, sputtered atom/molecule energy, etc., which affect film properties as noted above and known in the art. Dynamic deposition rate is one way to quantify multiple process and geometric parameters which together result in a time and size dependent film deposition rate on the substrate. Substrate temperature can affect film growth rate as well as the energy available to help atoms/molecules rearrange on the substrate surface, which is why high temperature processes are typically used to maximize film density and hardness. In preferred implementations, low temperature processes ($<350^{\circ}\text{C}$) are employed, as these lower temperatures allow for film deposition on chemically strengthened glass substrates without reducing the beneficial compressive stress formed in the surface of the chemically strengthened glass through processes such as ion-exchange.

[00112] According to some implementations of the sputtering methods (e.g., reactive, in-line and rotary metal-mode) of forming articles 100 described herein, including an optical film 130B of an anti-reflective coating 120, various parameters can be adjusted and controlled to optimize and tailor particular physical and optical properties of the as-formed optical structures. For example, embodiments of the method employ a sputtering throw distance that ranges from about 0.02 m to about 0.3 m, from about 0.05 m to about 0.2 m, from about 0.075 m to about 0.15 m, and all sputtering throw distances between these distances. For those sputtering processes employing cylindrical sputter targets, the length of these targets can range from about 0.1 m to about 4 m, from about 0.5 m to about 2 m, from about 0.75 m to about 1.5 m, and all target lengths between these lengths. Further, a cylindrical target can be employed at a sputter power from about 1 kW to about 100 kW, from about 10 kW to about 50 kW, and all sputter power values therebetween. In addition, a cylindrical target can be employed at a target power per length that ranges from about 0.25 kW/m to about 1000 kW/m, from about 1 kW/m to about 20 kW/m, and all power per length values therebetween.

[00113] According to further implementations of the sputtering methods (e.g., reactive, in-line and rotary metal-mode) of forming articles 100 described herein, including an optical film 130B of an anti-reflective coating 120, additional parameters can be adjusted and controlled to

optimize and tailor particular physical and optical properties of the as-formed optical structures. For example, embodiments of the method can employ a planar sputter target with a target total area that ranges from about 100 cm² to about 20000 cm², or from about 500 cm² to about 5000 cm², and all area values therebetween. Further, the planar sputter target power can be set within a range from about 1 kW to about 100 kW, from about 10 kW to about 50 kW, and all sputter power values therebetween. In addition, a planar target can be employed at a target power per total area that ranges from about 0.00005 kW/cm² to about 1 kW/cm², from about 0.0001 kW/cm² to about 0.01 kW/cm², and all power per total area values therebetween. Still further, a planar target can be employed at a target power per sputtered area that ranges from about 0.0002 kW/cm² to about 4 kW/cm², from about 0.0005 kW/cm² to about 0.05 kW/cm², and all power per sputtered area values therebetween.

[00114] In other implementations of the sputtering methods (e.g., reactive, in-line and rotary metal-mode) of forming articles 100 described herein, including an optical film 130B of an anti-reflective coating 120, various other parameters can be adjusted and controlled to optimize and tailor particular physical and optical properties of the as-formed optical structures. For example, the method can employ a dynamic deposition rate that ranges from about 0.1 nm*(m/s) to about 1000 nm*(m/s), from about 0.5 nm*(m/s) to about 100 nm*(m/s), all deposition rates therebetween. The sputter chamber pressure, as another example, can range from about 0.5 mTorr to about 25 mTorr, from about 2 mTorr to about 15 mTorr, from about 2 mTorr to about 10 mTorr, from about 4 mTorr to about 12 mTorr, 4 mTorr to about 10 mTorr, and all pressures between these values. As another example, the method can employ a sputtering power supply frequency that ranges from about 0 kHz to about 200 kHz, from about 15 KHz to about 75 kHz, from about 20 kHz to about 60 kHz, from about 10 kHz to about 50 kHz, and all power frequency levels therebetween.

[00115] According to other implementations of the sputtering methods (e.g., reactive, in-line and rotary metal-mode) of forming articles 100 described herein, including an optical film 130B of an anti-reflective coating 120, other parameters including sputtering temperature, sputtering target composition, and sputtering atmosphere can be adjusted and controlled to optimize and tailor particular physical and optical properties of the as-formed optical structures. With regard to temperature, the method can employ sputtering temperatures of less than 300°C, less than 250°C, less than 220°C, less than 200°C, less than 150°C, less than 125°C, less than 100°C, and

all sputtering temperatures below these values. With regard to sputtering target compositions, silicon (Si) targets in semiconducting, metallic and elemental forms can be employed. As it relates to atmosphere, various reactive and non-reactive gases can be employed according to these sputtering process, including argon, nitrogen, and oxygen, e.g., as incorporated into a plasma in some embodiments.

[00116] In addition, the foregoing processes can be employed to coat these films and optical structures over substrates of various sizes suitable for lab-scale and manufacturing-scale processes. For example, suitable substrate sizes include substrates that are larger than 30 cm², larger than 50 cm², larger than 100 cm², larger than 200 cm², or even larger than 400 cm².

[00117] In some embodiments, the method may include controlling the physical thickness of the anti-reflective coating 120 (e.g., including its layers 130A, 130B and 131) and/or the additional coating 140 so that it does not vary by more than about 4% along about 80% or more of the area of the anti-reflective surface 122 or from the target physical thickness for each layer at any point along the substrate area. In some embodiments, the physical thickness of the anti-reflective layer coating 120 and/or the additional coating 140 is controlled so that it does not vary by more than about 4% along about 95% or more of the area of the anti-reflective surface 122.

[00118] In some embodiments of the article 100 depicted in FIGS. 1-3, the anti-reflective coating 120 is characterized by a residual stress of less than about +50 MPa (tensile) to about -1000 MPa (compression). In some implementations of the article 100, the anti-reflective coating 120 is characterized by a residual stress from about -50 MPa to about -1000 MPa (compression), or from about -75 MPa to about -800 MPa (compression). Further, according to some implementations, one or more optical film(s) 130B of the anti-reflective coating 120 can be characterized by a residual stress from about -50 MPa (compression) to about -2500 MPa (compression), from about -100 MPa (compression) to about -1500 MPa (compression), and all residual stress values therebetween. Unless otherwise noted, residual stress in the anti-reflective coating 120 and/or its layers or optical film(s) is obtained by measuring the curvature of the substrate 110 before and after deposition of the anti-reflective coating 120, and then calculating residual film stress according to the Stoney equation according to principles known and understood by those with ordinary skill in the field of the disclosure.

[00119] The articles 100 disclosed herein (e.g., as shown in FIGS. 1-3) may be incorporated into a device article for example a device article with a display (or display device articles) (e.g.,

consumer electronics, including mobile phones, tablets, computers, navigation systems, wearable devices (e.g., watches) and the like), augmented-reality displays, heads-up displays, glasses-based displays, architectural device articles, transportation device articles (e.g., automotive, trains, aircraft, sea craft, etc.), appliance device articles, or any device article that benefits from some transparency, scratch-resistance, abrasion resistance or a combination thereof. An exemplary device article incorporating any of the articles disclosed herein (e.g., as consistent with the articles 100 depicted in FIGS. 1-3) is shown in FIGS. 4A and 4B. Specifically, FIGS. 4A and 4B show a consumer electronic device 400 including a housing 402 having a front 404, a back 406, and side surfaces 408; electrical components (not shown) that are at least partially inside or entirely within the housing and including at least a controller, a memory, and a display 410 at or adjacent to the front surface of the housing; and a cover substrate 412 at or over the front surface of the housing such that it is over the display. In some embodiments, the cover substrate 412 may include any of the articles disclosed herein. In some embodiments, at least one of a portion of the housing or the cover glass comprises the articles disclosed herein.

[00120] According to some embodiments, the articles 100 (e.g., as shown in FIGS. 1-3) may be incorporated within a vehicle interior with vehicular interior systems, as depicted in FIG. 5. More particularly, the article 100 may be used in conjunction with a variety of vehicle interior systems. A vehicle interior 540 is depicted that includes three different examples of a vehicle interior system 544, 548, 552. Vehicle interior system 544 includes a center console base 556 with a surface 560 including a display 564. Vehicle interior system 548 includes a dashboard base 568 with a surface 572 including a display 576. The dashboard base 568 typically includes an instrument panel 580 which may also include a display. Vehicle interior system 552 includes a dashboard steering wheel base 584 with a surface 588 and a display 592. In one or more examples, the vehicle interior system may include a base that is an armrest, a pillar, a seat back, a floor board, a headrest, a door panel, or any portion of the interior of a vehicle that includes a surface. It will be understood that the article 100 described herein can be used interchangeably in each of vehicle interior systems 544, 548 and 552.

[00121] According to some embodiments, the articles 100 (e.g., as shown in FIGS. 1-3) may be used in a passive optical element, for example a lens, windows, lighting covers, eyeglasses, or sunglasses, that may or may not be integrated with an electronic display or electrically active device.

[00122] Referring again to FIG. 5, the displays 564, 576 and 592 may each include a housing having front, back, and side surfaces. At least one electrical component is at least partially within the housing. A display element is at or adjacent to the front surface of the housings. The article 100 (see FIGS. 1-3) is disposed over the display elements. It will be understood that the article 100 may also be used on, or in conjunction with, the armrest, the pillar, the seat back, the floor board, the headrest, the door panel, or any portion of the interior of a vehicle that includes a surface, as explained above. According to various examples, the displays 564, 576 and 592 may be a vehicle visual display system or vehicle infotainment system. It will be understood that the article 100 may be incorporated in a variety of displays and structural components of autonomous vehicles and that the description provided herein with relation to conventional vehicles is not limiting.

EXAMPLES

[00123] Various embodiments will be further clarified by the following examples.

EXAMPLE 1

[00124] The as-fabricated samples of Example 1 (“Ex. 1”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having five (5) layers on the glass substrate, as shown in FIG. 2B and Table 1 below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00125] The modeled samples of Example 1 (“Ex. 1-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 1 below. Optical properties reported for all examples were measured at near-normal incidence, unless otherwise noted.

Table 1: Anti-reflective coating attributes for Example 1

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 1-M	Ex. 1
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	84.7	86.0
130B	Si _x N _y	2.05	96.1	97.9
130A	SiO ₂	1.48	21.2	21.7
130B	Si _x N _y	2.05	20.3	20.1
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			247.3	250.7
Reflected color	Y		0.35	0.28
	L*		3.2	5.8
	a*		-1.2	0.9
	b*		-2.7	-5.7
Hardness (GPa)	@ 100 nm depth			10.6
	@ 500 nm depth			8.8
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			11.4
	Depth (nm)			147.0
Film stress	(MPa)			-466
Surface roughness, R_a	(nm)			0.83

EXAMPLE 2

[00126] The as-fabricated samples of Example 2 (“Ex. 2”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having five (5) layers on the glass substrate, as shown in FIG. 2B and Table 2 below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00127] The modeled samples of Example 2 (“Ex. 2-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 2 below.

Table 2: Anti-reflective coating attributes for Example 2

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 2-M	Ex. 2
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	81.7	81.1
130B	Si _x N _y	2.05	119.0	117.8
130A	SiO ₂	1.48	33.3	32.7
130B	Si _x N _y	2.05	14.2	14.4
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			273.2	271.0
Reflected color	Y		0.56	0.47
	L*		5.1	6.4
	a*		-1.5	-0.3
	b*		-3.4	-3.7
Hardness (GPa)	@ 100 nm depth			11.1
	@ 500 nm depth			8.9
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			11.8
	Depth (nm)			135.0
Film stress	(MPa)			-521
Surface roughness, R_a	(nm)			0.91

EXAMPLE 3

[00128] The as-fabricated samples of Example 3 (“Ex. 3”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having five (5) layers on the glass substrate, as shown in FIG. 2B and Table 3 below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00129] The modeled samples of Example 3 (“Ex. 3-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 3 below.

Table 3: Anti-reflective coating attributes for Example 3

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 3-M	Ex. 3
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	90.7	89.7
130B	Si _x N _y	2.05	70.0	69.9
130A	SiO ₂	1.48	23.3	21.5
130B	Si _x N _y	2.05	27.5	27.5
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			236.5	233.6
Reflected color	Y		0.28	0.24
	L*		2.5	2.9
	a*		0.1	-0.9
	b*		-3.1	-1.3
Hardness (GPa)	@ 100 nm depth			10.5
	@ 500 nm depth			8.9
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			10.7
	Depth (nm)			135.0
Film stress	(MPa)			-523
Surface roughness, R_a	(nm)			0.83

EXAMPLE 3A

[00130] The as-fabricated samples of Example 3A (“Ex. 3A”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having five (5) layers on the glass substrate, as shown in FIG. 2B and Table 3A below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00131] The modeled samples of Example 3A (“Ex. 3-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 3A below.

Table 3A: Anti-reflective coating attributes for Example 3A

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 3-M	Ex. 3A
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	90.7	90.8
130B	Si _x N _y	2.05	70.0	73.5
130A	SiO ₂	1.48	23.3	20.6
130B	Si _x N _y	2.05	27.5	27.4
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			236.5	237.4
Reflected color	Y		0.28	0.24
	L*		2.5	4.3
	a*		0.1	0.7
	b*		-3.1	-3.7
Hardness (GPa)	@ 100 nm depth			10.2
	@ 500 nm depth			8.8
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			10.5
	Depth (nm)			135.0
Film stress	(MPa)			-517
Surface roughness, R_a	(nm)			0.85

EXAMPLE 4

[00132] The as-fabricated samples of Example 4 (“Ex. 4”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having seven (7) layers on the glass substrate, as shown in FIG. 2A and Table 4 below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00133] The modeled samples of Example 4 (“Ex. 4-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 4 below.

Table 4: Anti-reflective coating attributes for Example 4

Reference No. (see FIG. 2A)	Material	Refractive Index	Ex. 4-M	Ex. 4
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	87.0	89.5
130B	Si _x N _y	2.05	135.1	136.1
130A	SiO ₂	1.48	9.3	9.2
130B	Si _x N _y	2.05	135.7	138.3
130A	SiO ₂	1.48	28.0	28.1
130B	Si _x N _y	2.05	19.7	19.9
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			439.7	446.1
Reflected color	Y		0.41	0.39
	L*		3.7	6.5
	a*		-0.8	-3.0
	b*		-4.0	-5.1
Hardness (GPa)	@ 100 nm depth			11.3
	@ 500 nm depth			10.3
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			13.5
	Depth (nm)			172.0
Film stress	(MPa)			-724
Surface roughness, R_a	(nm)			1.00

EXAMPLE 5

[00134] The as-fabricated samples of Example 5 (“Ex. 5”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having five (5) layers on the glass substrate, as shown in FIG. 2B and Table 5 below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00135] The modeled samples of Example 5 (“Ex. 5-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 5A below.

Table 5A: Anti-reflective coating attributes for Example 5

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 5-M	Ex. 5
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	82.2	81.9
130B	Si _x N _y	2.05	225.0	226.6
130A	SiO ₂	1.48	15.7	16.7
130B	Si _x N _y	2.05	28.2	27.9
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			376.0	378.0
Reflected color	Y		0.80	0.77
	L*		7.2	10.2
	a*		-2.0	-1.2
	b*		-4.4	-5.5
Hardness (GPa)	@ 100 nm depth			11.9
	@ 500 nm depth			9.7
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			13.7
	Depth (nm)			200.0
Film stress	(MPa)			-770
Surface roughness, R_a	(nm)			0.99

EXAMPLE 5A

[00136] The as-fabricated samples of Example 5A (“Ex. 5A”) were formed by providing a glass substrate having a nominal composition of 69 mol% SiO₂, 10 mol% Al₂O₃, 15 mol% Na₂O, and 5 mol% MgO and disposing an anti-reflective coating having five (5) layers on the glass substrate, as shown in FIG. 2B and Table 5B below. The anti-reflective coating (e.g., as consistent with the anti-reflective coatings 120 outlined in the disclosure) of each of the as-fabricated samples in this Example was deposited using a reactive sputtering process.

[00137] The modeled samples of Example 5A (“Ex. 5-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Further, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 5A below.

Table 5B: Anti-reflective coating attributes for Example 5A

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 5-M	Ex. 5A
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	82.2	85.1
130B	Si _x N _y	2.05	225.0	220.9
130A	SiO ₂	1.48	15.7	19.6
130B	Si _x N _y	2.05	28.2	27.8
130A	SiO ₂	1.48	25.0	25.0
110	Glass substrate	1.51		
Total thickness			376.0	378.5
Reflected color	Y		0.80	0.88
	L*		7.2	9.4
	a*		-2.0	-3.5
	b*		-4.4	-2.5
Hardness (GPa)	@ 100 nm depth			10.9
	@ 500 nm depth			9.7
Max hardness (from 100 nm to 500 nm depth)	Hmax (GPa)			12.8
	Depth (nm)			172.0
Film stress	(MPa)			-78
Surface roughness, R_a	(nm)			1.03

[00138] Referring now to FIG. 6, a plot of hardness vs. indentation depth for the as-fabricated articles of Examples 1, 2, 3, 4, 5 and 5A is provided. The data shown in FIG. 6 was generated by employing a Berkovich Indenter Hardness Test on the samples of Examples 1-5A. As is evident from FIG. 6, hardness values peak at an indentation depth from 150 to 250 nm. Further, the as-fabricated samples of Examples 4, 5 and 5A exhibited the highest hardness values at indentation depths of 100 nm and 500 nm, and the highest maximum hardness values within the indentation depth from 100 nm to 500 nm.

[00139] Referring now to FIG. 7, a plot is provided of first-surface, reflected color coordinates measured at, or estimated for, near-normal incidence of the samples outlined above in Examples 1-5A. As is evident from FIG. 7, there is a fairly good correlation between the color coordinates exhibited by the as-fabricated and modeled samples from each of the Examples. Further, the color coordinates exhibited by the samples shown in FIG. 7 are indicative of limited color shifting associated with the anti-reflective coatings of the disclosure.

EXAMPLE 6

[00140] Example 6 is directed to two sets of modeled samples. In particular, the modeled samples of Example 6 (“Ex. 3-M” and “Ex. 6-M”) were assumed to employ a glass substrate having the same composition of the glass substrate employed in the as-fabricated samples of this example. Note that the Ex. 3-M modeled sample in Example 6 employs the same configuration of the anti-reflective coating as employed in Example 3, i.e., Ex. 3-M. The Ex. 6-M sample, however, has a similar anti-reflective coating configuration, but with a thicker low RI layer in contact with the substrate. More particularly, the anti-reflective coating of each of the modeled samples was assumed to have the layer materials and physical thickness as shown in Table 6 below. As is evident from the data shown in Table 6, the Ex. 6-M sample exhibits an even lower photopic average reflectance (i.e., Y value) as compared to the modeled sample, Ex. 3-M.

Table 6: Anti-reflective coating attributes for Example 6

Reference No. (see FIG. 2B)	Material	Refractive Index	Ex. 3-M	Ex. 6-M
			Thickness (nm)	
N/A	Air	1.0		
131	SiO ₂	1.48	90.7	89.3
130B	Si _x N _y	2.05	70.0	70.0
130A	SiO ₂	1.48	23.3	26.3
130B	Si _x N _y	2.05	27.5	23.5
130A	SiO ₂	1.48	25.0	53.6
110	Glass substrate	1.51		
Total thickness			236.5	262.62
Reflected color	Y		0.28	0.196
	L*		2.5	1.8
	a*		0.1	4.3
	b*		-3.1	-5.2

[00141] Referring now to FIG. 8, a plot of specular component excluded (SCE) values is provided for samples of the prior Examples, specifically, Exs. 1-5, as obtained from samples subjected to the Alumina SCE Test. Further, SCE values are also reported from a comparative article (“Comp. Ex. 1”), which includes the same substrate as employed in Exs. 1-5 and has a conventional anti-reflective coating comprising niobia and silica. Notably, the samples from Examples 1-5 of the disclosure (i.e., Exs. 1-5) exhibited SCE values of about 0.2% or less, three

times (or more) lower than the SCE value reported for the comparative sample (Comp. Ex. 1). As noted earlier, lower SCE values are indicative of less severe abrasion-related damage.

[00142] Referring now to FIG. 9, a plot is provided of hardness (GPa) vs. indentation depth (nm) for a hardness test stack of high refractive index layer material (i.e., a material suitable for a high RI index layer 130B as shown in FIGS. 2A and 2B) comprising SiN_x , consistent with a high RI layer 130B, according to the disclosure. Notably, the plot in FIG. 9 was obtained by employing the Berkovich Indenter Hardness Test on a test stack comprising a substrate consistent with those in Examples 1-5A and a high index RI layer comprising SiN_x having a thickness of about 2 microns, to minimize the influence of the substrate and the other test-related articles described earlier in the disclosure. Accordingly, the hardness values observed in FIG. 9 on the 2 micron-thick sample are indicative of the actual intrinsic material hardness of the much thinner, high RI layers employed in the anti-reflective coatings 120 of the disclosure.

EXAMPLE 7

[00143] Example 7 is directed to the formation of optical films over a glass substrate, as consistent with the optical article 100 depicted in FIG. 2C. More particularly, the optical films of this example comprise SiN_x or SiO_xN_y and were formed according to a rotary, metal mode sputtering process according to the process parameters depicted in Table 7 below. In forming these optical films according to the rotary, metal-mode sputtering methods outlined in the disclosure, it was evident that metal-like sputtering occurred in the region of the sputtering target and a reaction to nitride or oxynitride occurred in the inductively coupled plasma (ICP) region within the sputtering chamber.

[00144] As noted in Table 7 below, various process parameters were adjusted in the rotary, metal-mode sputtering method employed to create the SiN_x or SiO_xN_y optical films. These parameters include: # of sputtering targets, power applied to each target (kW), total target power (kW), argon (Ar) gas flow at the sputtering target (sccm), ICP power (kW), argon (Ar) gas flow in the ICP region (sccm), nitrogen (N_2) gas flow in the ICP region (sccm) and oxygen (O_2) gas flow in the ICP region (sccm). As also noted in Table 7, various properties were measured on the optical films of this example. These properties include: refractive index (n), as measured at 550 nm; extinction coefficient (k), as measured at 400 nm; film thickness (nm); film residual stress (MPa), with negative values indicative of residual stress in compression; and Berkovich hardness (GPa), as measured at a depth of 500 nm.

Table 7: Properties and process parameters for optical films made with rotary metal-mode sputtering process for Example 7

Optical film	Process settings								Measured film properties				
	# of targets	Power to each target, kW	Total target power, kW	Ar per target, sccm	ICP Power, kW	ICP Ar, sccm	ICP N ₂ , sccm	ICP O ₂ , sccm	(n) at 550 nm	(k) at 400 nm	film thick, nm	film stress, MPa	Hardness @ 500 nm, GPa
SiO _x N _y	4	8	32	110	3	80	200	20	2.034	6.04E-03	2144	-895	20.8
SiN _x	4	7	28	480	4	80	200	0	2.014	7.50E-04	2000	-50	21.0
SiO _x N _y	4	9	36	110	4	80	200	30	2.016	5.43E-03	2189	-886	21.2
SiO _x N _y	4	8	32	110	3	80	200	10	2.087	9.30E-03	2108	-955	21.6
SiO _x N _y	4	9	36	110	4	80	200	20	2.007	1.97E-03	2175	-906	21.7
SiO _x N _y	4	9	36	110	4	80	200	20	2.058	8.22E-03	2173	-844	21.7
SiO _x N _y	4	7	28	110	3	80	200	10	2.008	5.66E-04	2131	-876	21.8
SiO _x N _y	4	8	32	110	4	80	250	20	2.002	6.27E-04	2041	-981	21.9
SiO _x N _y	4	7	28	110	4	80	200	10	2.002	4.17E-04	2138	-941	22.0
SiO _x N _y	4	6	24	110	4	80	200	10	2.016	5.62E-04	1953	-2448	22.2
SiO _x N _y	4	8	32	110	4	80	200	10	2.018	8.28E-04	2130	-943	22.2
SiN _x	4	6	24	110	4	80	200	0	2.053	6.36E-04	1560	-1135	22.5
SiO _x N _y	3	7	21	110	3	80	200	5	2.040	9.39E-04	1841	-1141	22.5
SiN _x	3	6	18	110	2	80	100	0	2.092	6.48E-03	2057	-930	22.7
SiN _x	3	8	24	110	4	80	150	0	2.046	6.31E-04	1960	-1155	22.8
SiO _x N _y	3	7	21	110	3	80	150	5	2.051	6.80E-04	1946	-1182	22.9
SiN _x	3	7	21	110	3	80	200	0	2.034	4.58E-04	1866	-768	22.9
SiN _x	4	7	28	180	4	80	200	0	2.058	8.25E-04	2000	-1000	25.0

EXAMPLE 8

[00145] Example 8 is directed to the formation of optical films over a glass substrate, as consistent with the optical article 100 depicted in FIG. 2C. More particularly, the optical films of this example comprise SiN_x and were formed according to an in-line sputtering process according to the process parameters depicted in Table 8 below.

[00146] As noted in Table 8 below, various process parameters were adjusted in the in-line sputtering method employed to create the SiN_x optical films. These parameters include: power applied to the target (kW), the frequency of the power of the target (kHz), argon (Ar) gas flow (sccm), nitrogen (N₂) gas flow (sccm), oxygen (O₂) gas flow (sccm) (i.e., 0 sccm for all films in this example), gas flow pressure (mTorr), and film deposition rate (nm*m/min). As also noted in Table 8, various properties were measured on the optical films of this example. These properties

include: optical film thickness (nm), refractive index (n), as measured at 550 nm; extinction coefficient (k), as measured at 400 nm; film residual stress (MPa), with negative values indicative of residual stress in compression; and Berkovich maximum hardness (GPa), as obtained from the hardness data obtained through the entire depth of each film.

Table 8: Properties and process parameters for optical films made with in-line sputtering process for Example 8

Optical film	Process settings							Measured film properties				
	Power (kw)	Power v, kHz	Ar flow, sccm	N ₂ flow, sccm	O ₂ flow, sccm	Pres, mTorr	dep rate, nm*m/min	film thick, nm	(n) at 550 nm	(k) at 400 nm	film stress, Mpa	Max. hardness, Gpa
SiN _x	36	45	785	490	0	9	104.8	466	2.035	4.18E-05	-257	22.4
SiN _x	36	45	377	348	0	4.5	114.3	508	2.071	3.98E-05	-1208	19.4
SiN _x	36	45	555	520	0	7.5	98.8	439	2.039	1.78E-03	-786	19.1
SiN _x	36	25	360	450	0	4.5	98.1	436	2.044	1.00E-03	-1253	19.0
SiN _x	36	45	475	438	0	6	102.8	457	2.046	3.70E-05	-1044	18.9
SiN _x	36	45	620	580	0	9	91.7	407	2.032	4.58E-03	-619	18.6
SiN _x	36	45	667	409	0	7.5	115.9	515	2.060	6.59E-05	-1115	18.6
SiN _x	36	45	830	460	0	9	113.7	379	2.030	5.66E-03	-209	18.4
SiN _x	30	45	555	520	0	7.5	97.4	512	2.035	4.27E-03	-833	18.3
SiN _x	36	45	452	624	0	7.5	83.7	372	2.038	5.70E-03	-990	18.2
SiN _x	36	45	875	400	0	9	124.4	711	2.045	3.03E-05	-160	18

EXAMPLE 9

[00147] Example 9 is directed to the formation of optical films over a glass substrate, as consistent with the optical article 100 depicted in FIG. 2C. More particularly, the optical films of this example comprise SiN_x and were formed according to a reactive sputtering process employing a single-chamber, box-type sputtering apparatus, as conducted according to the process parameters depicted in Table 9 below.

[00148] As noted in Table 9 below, various process parameters were adjusted in the in-line sputtering method employed to create the SiN_x optical films. These parameters include: power applied to the target (kW), argon (Ar) gas flow (sccm), nitrogen (N₂) gas flow (sccm), oxygen (O₂) gas flow (sccm) (i.e., 0 sccm for all films in this example), and gas flow pressure (mTorr). As also noted in Table 9, various properties were measured on the optical films of this example.

These properties include: optical film thickness (nm), refractive index (n), as measured at 550 nm; extinction coefficient (k), as measured at 300 nm; film residual stress (MPa), with negative values indicative of residual stress in compression; Berkovich maximum hardness (GPa), as obtained from the hardness data obtained through the entire depth of each film; and surface roughness (R_a) of each film (nm), as measured over a $2\ \mu\text{m} \times 2\ \mu\text{m}$ test area.

Table 9: Properties and process parameters for optical films made with reactive sputtering process for Example 9

Optical film	Process settings					Measured film properties					
	Power, kW	Ar flow, sccm	N ₂ flow, sccm	O ₂ flow, sccm	P, mTorr	film thick, nm	(n) at 550 nm	(k) at 300 nm	film stress, MPa	Max. hardness (Gpa)	R _a , nm 2x2 μm msmt. area
SiN _x	0.5	30	30	0	2	663	2.047	1.01E-04	-1722	21.1	0.917
SiN _x	0.5	30	30	0	3	593	2.048	3.94E-04	-897	20.3	1.18
SiN _x	0.5	30	30	0	4	557	2.027	1.11E-03	-286	19.5	1.48
SiN _x	0.5	30	30	0	5	514	1.994	3.49E-03	-241	17.2	1.81

[00149] As used herein, the “AlO_xN_y,” “SiO_xN_y,” and “Si_uAl_xO_yN_z” materials in the disclosure include various aluminum oxynitride, silicon oxynitride and silicon aluminum oxynitride materials, as understood by those with ordinary skill in the field of the disclosure, described according to certain numerical values and ranges for the subscripts, “u,” “x,” “y,” and “z”. That is, it is common to describe solids with “whole number formula” descriptions, for example Al₂O₃. It is also common to describe solids using an equivalent “atomic fraction formula” description for example Al_{0.4}O_{0.6}, which is equivalent to Al₂O₃. In the atomic fraction formula, the sum of all atoms in the formula is $0.4 + 0.6 = 1$, and the atomic fractions of Al and O in the formula are 0.4 and 0.6 respectively. Atomic fraction descriptions are described in many general textbooks and atomic fraction descriptions are often used to describe alloys. See, for example: (i) Charles Kittel, Introduction to Solid State Physics, seventh edition, John Wiley & Sons, Inc., NY, 1996, pp. 611-627; (ii) Smart and Moore, Solid State Chemistry, An introduction, Chapman & Hall University and Professional Division, London, 1992, pp. 136-151; and (iii) James F.

Shackelford, Introduction to Materials Science for Engineers, Sixth Edition, Pearson Prentice Hall, New Jersey, 2005, pp. 404-418.

[00150] Again referring to the “ AlO_xN_y ,” “ SiO_xN_y ,” and “ $\text{Si}_u\text{Al}_x\text{O}_y\text{N}_z$ ” materials in the disclosure, the subscripts allow those with ordinary skill in the art to reference these materials as a class of materials without specifying particular subscript values. To speak generally about an alloy, for example aluminum oxide, without specifying the particular subscript values, we can speak of Al_vO_x . The description Al_vO_x can represent either Al_2O_3 or $\text{Al}_{0.4}\text{O}_{0.6}$. If $v + x$ were chosen to sum to 1 (i.e. $v + x = 1$), then the formula would be an atomic fraction description. Similarly, more complicated mixtures can be described, for example $\text{Si}_u\text{Al}_v\text{O}_x\text{N}_y$, where again, if the sum $u + v + x + y$ were equal to 1, we would have the atomic fractions description case.

[00151] Once again referring to the “ AlO_xN_y ,” “ SiO_xN_y ,” and “ $\text{Si}_u\text{Al}_x\text{O}_y\text{N}_z$ ” materials in the disclosure, these notations allow those with ordinary skill in the art to readily make comparisons to these materials and others. That is, atomic fraction formulas are sometimes easier to use in comparisons. For instance; an example alloy consisting of $(\text{Al}_2\text{O}_3)_{0.3}(\text{AlN})_{0.7}$ is closely equivalent to the formula descriptions $\text{Al}_{0.448}\text{O}_{0.31}\text{N}_{0.241}$ and also $\text{Al}_{367}\text{O}_{254}\text{N}_{198}$. Another example alloy consisting of $(\text{Al}_2\text{O}_3)_{0.4}(\text{AlN})_{0.6}$ is closely equivalent to the formula descriptions $\text{Al}_{0.438}\text{O}_{0.375}\text{N}_{0.188}$ and $\text{Al}_{37}\text{O}_{32}\text{N}_{16}$. The atomic fraction formulas $\text{Al}_{0.448}\text{O}_{0.31}\text{N}_{0.241}$ and $\text{Al}_{0.438}\text{O}_{0.375}\text{N}_{0.188}$ are relatively easy to compare to one another. For instance, Al decreased in atomic fraction by 0.01, O increased in atomic fraction by 0.065 and N decreased in atomic fraction by 0.053. It takes more detailed calculation and consideration to compare the whole number formula descriptions $\text{Al}_{367}\text{O}_{254}\text{N}_{198}$ and $\text{Al}_{37}\text{O}_{32}\text{N}_{16}$. Therefore, it is sometimes preferable to use atomic fraction formula descriptions of solids. Nonetheless, the use of $\text{Al}_v\text{O}_x\text{N}_y$ is general since it captures any alloy containing Al, O and N atoms.

[00152] As understood by those with ordinary skill in the field of the disclosure with regard to any of the foregoing materials (e.g., AlN) for the optical film 80, each of the subscripts, “u,” “x,” “y,” and “z,” can vary from 0 to 1, the sum of the subscripts will be less than or equal to one, and the balance of the composition is the first element in the material (e.g., Si or Al). In addition, those with ordinary skill in the field can recognize that “ $\text{Si}_u\text{Al}_x\text{O}_y\text{N}_z$ ” can be configured such that “u” equals zero and the material can be described as “ AlO_xN_y ”. Still further, the foregoing compositions for the optical film 80 exclude a combination of subscripts that would result in a pure elemental form (e.g., pure silicon, pure aluminum metal, oxygen gas, etc.). Finally, those

with ordinary skill in the art will also recognize that the foregoing compositions may include other elements not expressly denoted (e.g., hydrogen), which can result in non-stoichiometric compositions (e.g., SiN_x vs. Si_3N_4). Accordingly, the foregoing materials for the optical film can be indicative of the available space within a $\text{SiO}_2\text{-Al}_2\text{O}_3\text{-SiN}_x\text{-AlN}$ or a $\text{SiO}_2\text{-Al}_2\text{O}_3\text{-Si}_3\text{N}_4\text{-AlN}$ phase diagram, depending on the values of the subscripts in the foregoing composition representations.

[00153] Embodiment 1. An optical film structure is provided that includes: an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride. The optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film. Further, the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[00154] Embodiment 2. The article of Embodiment 1, wherein the optical film further comprises a residual stress in the range from about -50 MPa (compression) to about -2500 MPa (compression).

[00155] Embodiment 3. The article of Embodiment 1, wherein the optical film further comprises a residual stress in the range from about -100 MPa (compression) to about -1500 MPa (compression).

[00156] Embodiment 4. The article according to any one of Embodiments 1-3, wherein the physical thickness of the optical film is from about 200 nm to about 3000 nm, and further wherein the optical film exhibits a surface roughness (R_a) of less than 3.0 nm when deposited onto a glass substrate.

[00157] Embodiment 5. The article according to any one of Embodiments 1-3, wherein the physical thickness of the optical film is from about 200 nm to about 3000 nm, and further wherein the optical film exhibits a surface roughness (R_a) of less than 1.5 nm when deposited onto a glass substrate.

[00158] Embodiment 6. The article according any one of Embodiments 1-5, wherein the optical film exhibits a maximum hardness of greater than 20 GPa, as measured by a Berkovich

Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 5×10^{-3} at a wavelength of 400 nm.

[00159] Embodiment 7. The article according to any one of Embodiments 1-5, wherein the optical film exhibits a maximum hardness of greater than 22 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-3} at a wavelength of 400 nm.

[00160] Embodiment 8. An optical article is provided that includes: an inorganic oxide substrate comprising opposing major surfaces; and an optical film structure disposed on a first major surface of the inorganic oxide substrate, the optical film structure comprising an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride. The optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film. Further, the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[00161] Embodiment 9. The article according to Embodiment 8, wherein the optical film further comprises a residual stress in the range from about -100 MPa (compression) to about -1500 MPa (compression).

[00162] Embodiment 10. The article according to Embodiment 8 or 9, wherein the physical thickness of the optical film is from about 200 nm to about 3000 nm, and further wherein the optical film exhibits a surface roughness (R_a) of less than 1.5 nm when deposited onto a glass substrate.

[00163] Embodiment 11. The article according to any one of Embodiments 8-10, wherein the optical film exhibits a maximum hardness of greater than 20 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 5×10^{-3} at a wavelength of 400 nm.

[00164] Embodiment 12. The article according to any one of Embodiments 8-10, wherein the optical film exhibits a maximum hardness of greater than 22 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-3} at a wavelength of 400 nm.

[00165] Embodiment 13. An optical article is provided that includes: an inorganic oxide substrate comprising opposing major surfaces; and an optical film structure disposed on a first major surface of the inorganic oxide substrate, the optical film structure comprising a plurality of optical films. Each optical film comprises a physical thickness from about 50 nm to about 3000 nm, and one of a silicon-containing oxide, a silicon-containing nitride and a silicon-containing oxynitride. Each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride. Further, each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

[00166] Embodiment 14. The article according to Embodiment 13, wherein the plurality of optical films comprises at least one optical film comprising a silicon-containing oxide having a

maximum hardness of greater than 5 GPa, as measured by a Berkovich Indenter Hardness Test on a test sample over an indentation depth range from about 100 nm to about 500 nm.

[00167] Embodiment 15. The article according to Embodiment 13 or 14, further comprising: an anti-reflection (AR) coating disposed over the first major surface of the substrate, the AR coating having a single-side photopic average reflectance of less than 1%.

[00168] Embodiment 16. The article according to any one of Embodiments 13-15, wherein the article exhibits a* and b* values, in reflectance, from about -10 to +2, the a* and b* values each measured on the optical film structure at a near-normal incident illumination angle.

[00169] Embodiment 17. The article according to any one of Embodiments 13-16, wherein the article exhibits a* and b* values, in transmission, from about -2 to +2.

[00170] Embodiment 18. The article according to any one of Embodiments 13-17, wherein the article exhibits a maximum hardness of greater than 10 GPa, as as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm.

[00171] Embodiment 19. The article according to any one of Embodiments 13-17, wherein the article exhibits a maximum hardness of greater than 14 GPa, as as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm.

[00172] Embodiment 20. The article according to any one of Embodiments 13-17, wherein the article exhibits a maximum hardness of greater than 16 GPa, as as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm.

[00173] Embodiment 21. The article according to any one of Embodiments 13-20, wherein the inorganic oxide substrate comprises a glass selected from the group consisting of a soda lime glass, alkali aluminosilicate glass, alkali-containing borosilicate glass, and alkali aluminoborosilicate glass.

[00174] Embodiment 22. The article according to any one of Embodiments 13-21, wherein the glass is chemically strengthened and comprises a compressive stress (CS) layer with a peak CS of 250 MPa or more, the CS layer extending within the chemically strengthened glass from the first major surface to a depth of compression (DOC) of about 10 microns or more.

[00175] Embodiment 23. A method of making an optical film is provided that includes: providing a substrate comprising opposing major surfaces within a sputtering chamber; sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 750 nm to about 3000 nm, and a silicon-containing nitride or a

silicon-containing oxynitride, and removing the optical film and the substrate from the chamber. Further, the sputtering is conducted with a rotary, metal-mode sputtering process employing a plurality of sputter targets, a total sputtering power from about 10 kW to about 50 kW and an argon gas flow rate at each target from about 50 sccm to about 600 sccm.

[00176] Embodiment 24. The method of Embodiment 23, wherein the optical film comprises a residual stress from about -50 MPa (compression) to about -2500 MPa (compression).

[00177] Embodiment 25. The method of Embodiment 23 or 24, wherein the optical film exhibits a hardness of greater than 20 GPa, as measured by a Berkovich Indenter Hardness Test at an indentation depth of 500 nm.

[00178] Embodiment 26. The method of any one of Embodiments 23-25, wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 2.0 at a wavelength of 550 nm.

[00179] Embodiment 27. A method of making an optical film is provided that includes: providing a substrate comprising opposing major surfaces within a sputtering chamber; sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 50 nm to about 1000 nm, and a silicon-containing nitride or a silicon-containing oxynitride, and removing the optical film and the substrate from the chamber. Further, the sputtering is conducted with an in-line sputtering process employing a sputter target, a sputtering power from about 10 kW to about 50 kW, a sputter power frequency from about 15 kHz to about 75 kHz, an argon gas flow rate from about 200 sccm to about 1000 sccm, and a sputter chamber pressure from about 2 mTorr to about 10 mTorr.

[00180] Embodiment 28. The method of Embodiment 27, wherein the optical film comprises a residual stress from about -100 MPa (compression) to about -1500 MPa (compression).

[00181] Embodiment 29. The method of Embodiment 27 or 28, wherein the optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film.

[00182] Embodiment 30. The method of any one of Embodiments 27-29, wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 2.0 at a wavelength of 550 nm.

[00183] Embodiment 31. A method of making an optical film is provided that includes: providing a substrate comprising opposing major surfaces within a sputtering chamber; sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 50 nm to about 1000 nm, and a silicon-containing nitride or a silicon-containing oxynitride, and removing the optical film and the substrate from the chamber. Further, the sputtering is conducted with a reactive sputtering process employing a sputter target, a sputtering power from about 0.1 kW to about 5 kW, an argon gas flow rate from about 10 sccm to about 100 sccm, and a sputter chamber pressure from about 1 mTorr to about 10 mTorr.

[00184] Embodiment 32. The method of Embodiment 31, wherein the optical film comprises a residual stress from about -100 MPa (compression) to about -2000 MPa (compression).

[00185] Embodiment 33. The method of Embodiment 31 or 32, wherein the optical film exhibits a maximum hardness of greater than 16 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film.

[00186] Embodiment 34. The method of any one of Embodiments 31-33, wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 300 nm and a refractive index (n) of greater than 2.0 at a wavelength of 550 nm.

[00187] Embodiment 35. A consumer electronic product is provided that includes: a housing comprising a front surface, a back surface and side surfaces; electrical components at least partially within the housing, the electrical components comprising a controller, a memory, and a display, the display at or adjacent the front surface of the housing; and a cover substrate disposed over the display. Further, at least one of a portion of the housing or the cover substrate comprises the optical film structure of any of the optical film structure of Embodiments 1-7 or the optical article of any one of Embodiments 8-22.

[00188] Many variations and modifications may be made to the above-described embodiments of the disclosure without departing substantially from the spirit and various principles of the

disclosure. All such modifications and variations are intended to be included herein within the scope of this disclosure and protected by the following claims. For example, the various features of the disclosure may be combined according to the following embodiments.

What is claimed is:

1. An optical film structure, comprising:
an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and
a silicon-containing nitride or a silicon-containing oxynitride,
wherein the optical film exhibits a maximum hardness of greater than 18 GPa, as
measured by a Berkovich Indenter Hardness Test over an indentation depth range from about
100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical
thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film
having the same composition as the optical film, and
further wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of
550 nm.
2. The film structure according to claim 1, wherein the optical film further comprises a
residual stress in the range from about -50 MPa (compression) to about -2500 MPa
(compression).
3. The film structure according to claim 1, wherein the optical film further comprises a
residual stress in the range from about -100 MPa (compression) to about -1500 MPa
(compression).
4. The film structure according to any one of claims 1-3, wherein the physical thickness of
the optical film is from about 200 nm to about 3000 nm, and further wherein the optical film
exhibits a surface roughness (R_a) of less than 3.0 nm when deposited onto a glass substrate.
5. The film structure according to any one of claims 1-3, wherein the physical thickness of
the optical film is from about 200 nm to about 3000 nm, and further wherein the optical film
exhibits a surface roughness (R_a) of less than 1.5 nm when deposited onto a glass substrate.

6. The film structure according to any one of claims 1-5, wherein the optical film exhibits a maximum hardness of greater than 20 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 5×10^{-3} at a wavelength of 400 nm.

7. The film structure according to any one of claims 1-5, wherein the optical film exhibits a maximum hardness of greater than 22 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-3} at a wavelength of 400 nm.

8. An optical article, comprising:
an inorganic oxide substrate comprising opposing major surfaces; and
an optical film structure disposed on a first major surface of the inorganic oxide substrate, the optical film structure comprising an optical film comprising a physical thickness from about 50 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride, wherein the optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and
further wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

9. The article according to claim 8, wherein the optical film further comprises a residual stress in the range from about -100 MPa (compression) to about -1500 MPa (compression).
10. The article according to claim 8 or claim 9, wherein the physical thickness of the optical film is from about 200 nm to about 3000 nm, and further wherein the optical film exhibits a surface roughness (R_a) of less than 1.5 nm when deposited onto a glass substrate.
11. The article according to any one of claims 8-10, wherein the optical film exhibits a maximum hardness of greater than 20 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 5×10^{-3} at a wavelength of 400 nm.
12. The article according to any one of claims 8-10, wherein the optical film exhibits a maximum hardness of greater than 22 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film, and further wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-3} at a wavelength of 400 nm.
13. An optical article, comprising:
an inorganic oxide substrate comprising opposing major surfaces; and
an optical film structure disposed on a first major surface of the inorganic oxide substrate, the optical film structure comprising a plurality of optical films,
wherein each optical film comprises a physical thickness from about 5 nm to about 3000 nm, and one of a silicon-containing oxide, a silicon-containing nitride and a silicon-containing oxynitride,

wherein each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride, and

further wherein each optical film comprising a silicon-containing nitride or a silicon-containing oxynitride exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 1.8 at a wavelength of 550 nm.

14. The article according to claim 13, wherein the plurality of optical films comprises at least one optical film comprising a silicon-containing oxide having a maximum hardness of greater than 5 GPa, as measured by a Berkovich Indenter Hardness Test on a test sample over an indentation depth range from about 100 nm to about 500 nm.

15. The article according to claim 13 or claim 14, further comprising:
an anti-reflection (AR) coating disposed over the first major surface of the substrate, the AR coating having a single-side photopic average reflectance of less than 1%.

16. The article according to any one of claims 13-15, wherein the article exhibits a^* and b^* values, in reflectance, from about -10 to +2, the a^* and b^* values each measured on the optical film structure at a near-normal incident illumination angle.

17. The article according to any one of claims 13-16, wherein the article exhibits a^* and b^* values, in transmission, from about -2 to +2.

18. The article according to any one of claims 13-17, wherein the article exhibits a maximum hardness of greater than 10 GPa, as as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm.

19. The article according to any one of claims 13-17, wherein the article exhibits a maximum hardness of greater than 14 GPa, as as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm.
20. The article according to any one of claims 13-17, wherein the article exhibits a maximum hardness of greater than 16 GPa, as as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm.
21. The article according to any one of claims 13-20, wherein the inorganic oxide substrate comprises a glass selected from the group consisting of a soda lime glass, alkali aluminosilicate glass, alkali-containing borosilicate glass, and alkali aluminoborosilicate glass.
22. The article according to any one of claims 13-21, wherein the glass is chemically strengthened and comprises a compressive stress (CS) layer with a peak CS of 250 MPa or more, the CS layer extending within the chemically strengthened glass from the first major surface to a depth of compression (DOC) of about 10 microns or more.
23. A method of making an optical film structure, comprising:
providing a substrate comprising opposing major surfaces within a sputtering chamber;
sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 750 nm to about 3000 nm, and a silicon-containing nitride or a silicon-containing oxynitride, and
removing the optical film and the substrate from the chamber,
wherein the sputtering is conducted with a rotary, metal-mode sputtering process employing a plurality of sputter targets, a total sputtering power from about 10 kW to about 50 kW and an argon gas flow rate at each target from about 50 sccm to about 600 sccm.
24. The method according to claim 23, wherein the optical film comprises a residual stress from about -50 MPa (compression) to about -2500 MPa (compression).

25. The method according to claim 23 or claim 24, wherein the optical film exhibits a hardness of greater than 20 GPa, as measured by a Berkovich Indenter Hardness Test at an indentation depth of 500 nm.

26. The method according to any one of claims 23-25, wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 2.0 at a wavelength of 550 nm.

27. A method of making an optical film structure, comprising:
providing a substrate comprising opposing major surfaces within a sputtering chamber;
sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 50 nm to about 1000 nm, and a silicon-containing nitride or a silicon-containing oxynitride, and
removing the optical film and the substrate from the chamber,
wherein the sputtering is conducted with an in-line sputtering process employing a sputter target, a sputtering power from about 10 kW to about 50 kW, a sputter power frequency from about 15 kHz to about 75 kHz, an argon gas flow from about 200 sccm to about 1000 sccm, and a sputter chamber pressure from about 2 mTorr to about 10 mTorr.

28. The method according to claim 27, wherein the optical film comprises a residual stress from about -100 MPa (compression) to about -1500 MPa (compression).

29. The method according to claim 27 or claim 28, wherein the optical film exhibits a maximum hardness of greater than 18 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film.

30. The method according to any one claims 27-29, wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 400 nm and a refractive index (n) of greater than 2.0 at a wavelength of 550 nm.

31. A method of making an optical film structure, comprising:
providing a substrate comprising opposing major surfaces within a sputtering chamber;
sputtering an optical film over a first major surface of the substrate, the optical film comprising a physical thickness from about 50 nm to about 1000 nm, and a silicon-containing nitride or a silicon-containing oxynitride, and
removing the optical film and the substrate from the chamber,
wherein the sputtering is conducted with a reactive sputtering process employing a sputter target, a sputtering power from about 0.1 kW to about 5 kW, an argon gas flow from about 10 sccm to about 100 sccm, and a sputter chamber pressure from about 1 mTorr to about 10 mTorr.

32. The method according to claim 31, wherein the optical film comprises a residual stress from about -100 MPa (compression) to about -2000 MPa (compression).

33. The method according to claim 31 or claim 32, wherein the optical film exhibits a maximum hardness of greater than 16 GPa, as measured by a Berkovich Indenter Hardness Test over an indentation depth range from about 100 nm to about 500 nm on a hardness test stack comprising a test optical film with a physical thickness of about 2 microns disposed on an inorganic oxide test substrate, the test optical film having the same composition as the optical film.

34. The method according to any one claims 31-33, wherein the optical film exhibits an optical extinction coefficient (k) of less than 1×10^{-2} at a wavelength of 300 nm and a refractive index (n) of greater than 2.0 at a wavelength of 550 nm.

35. A consumer electronic product, comprising:
- a housing comprising a front surface, a back surface and side surfaces;
 - electrical components at least partially within the housing, the electrical components comprising a controller, a memory, and a display, the display at or adjacent the front surface of the housing; and
 - a cover substrate disposed over the display,
- wherein at least one of a portion of the housing or the cover substrate comprises the optical film structure of any of the optical film structure of claims 1-7 or the optical article of any one of claims 8-22.

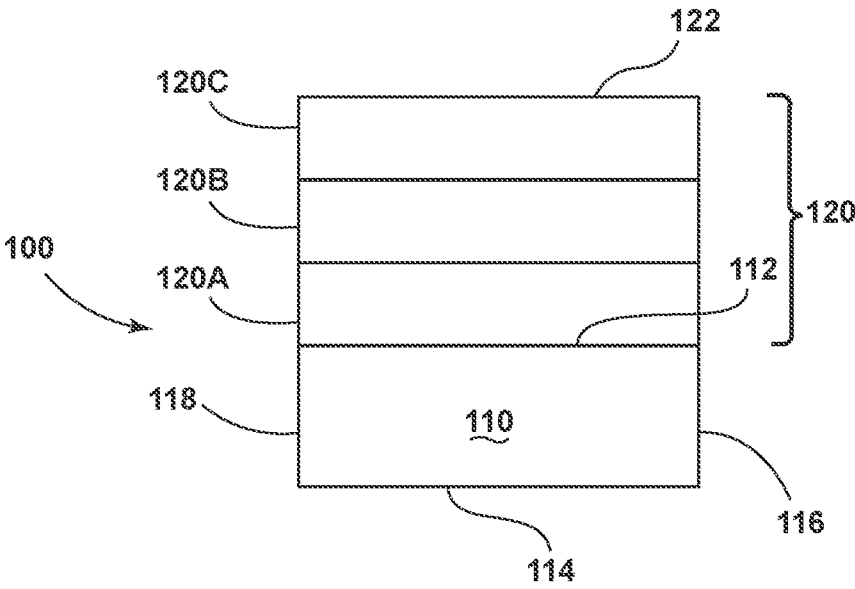


FIG. 1

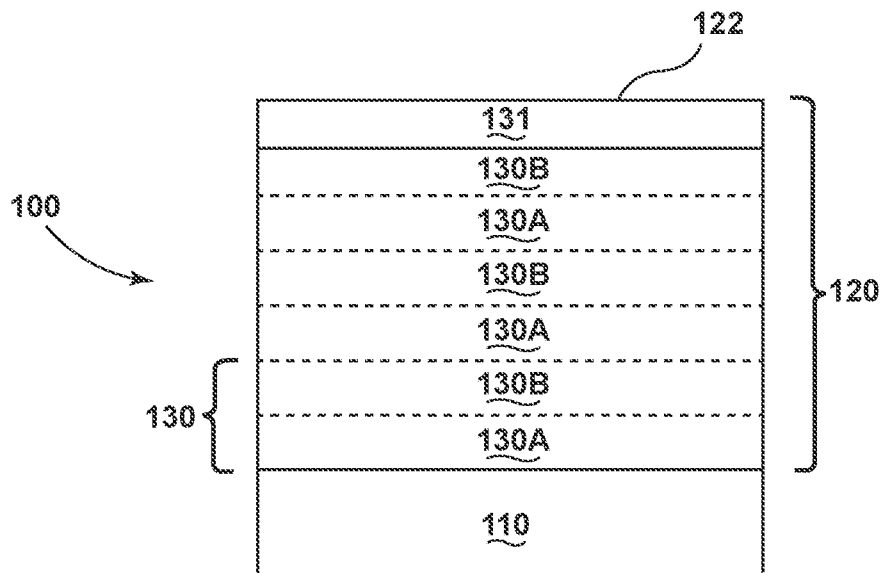


FIG. 2A

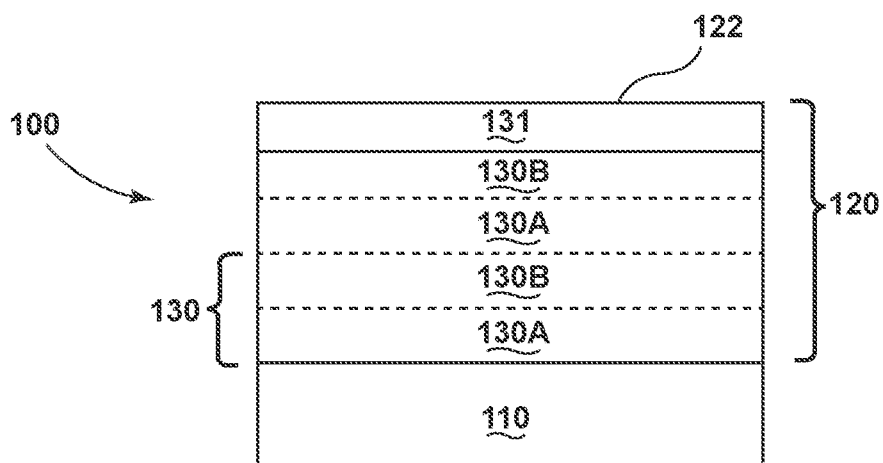


FIG. 2B

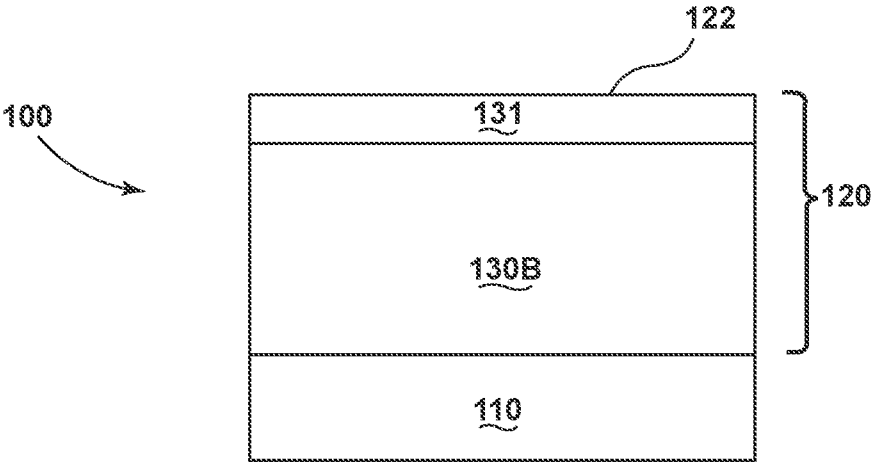


FIG. 2C

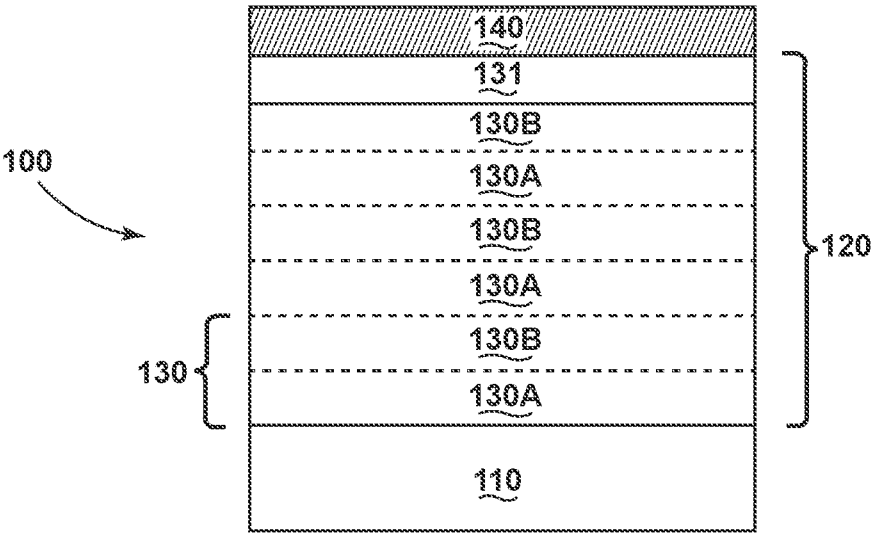
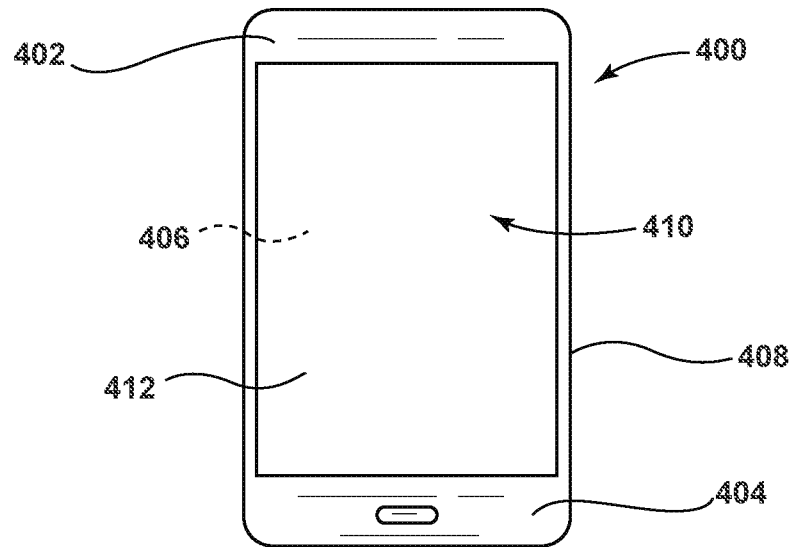
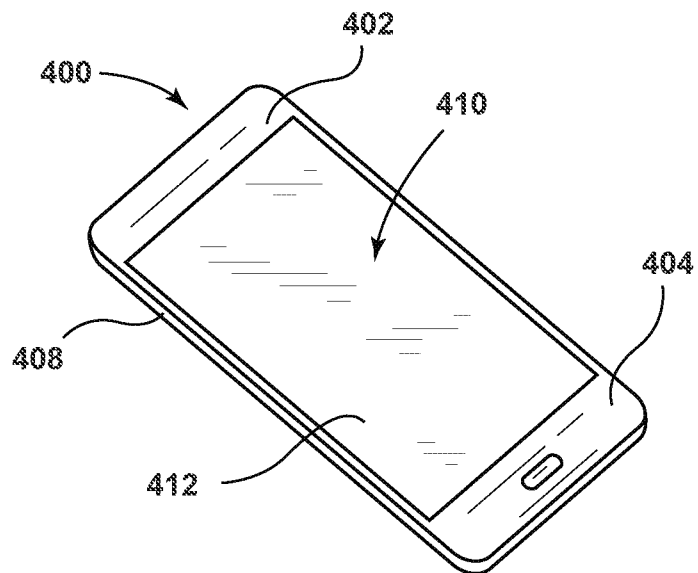


FIG. 3

**FIG. 4A****FIG. 4B**

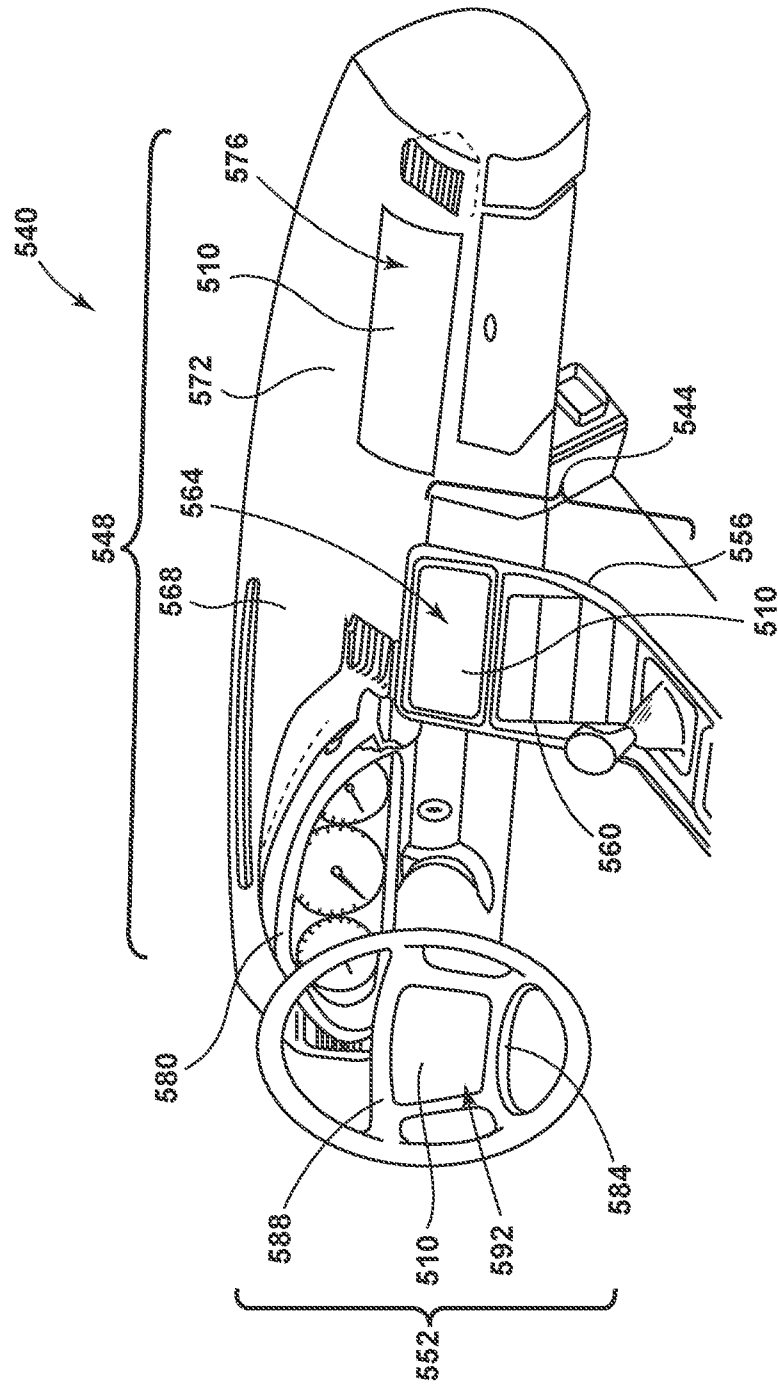


FIG. 5

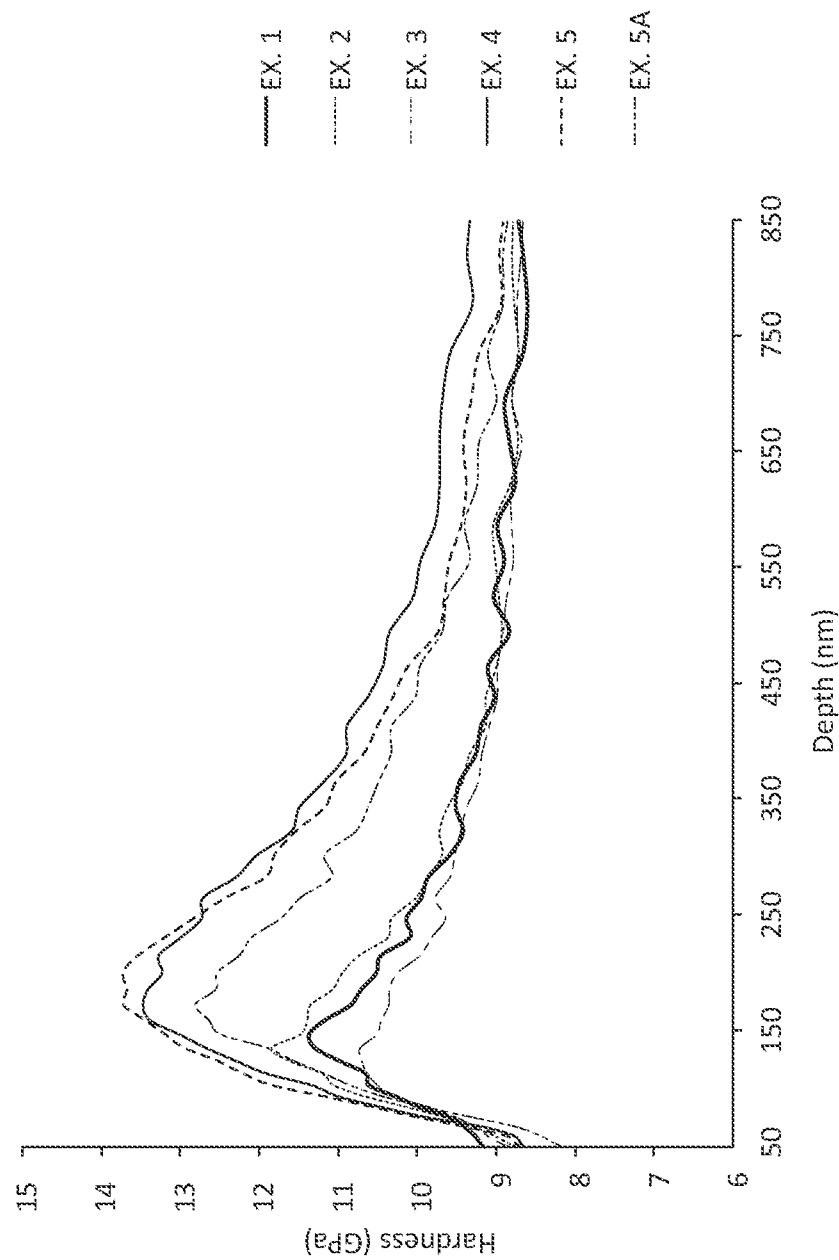


FIG. 6

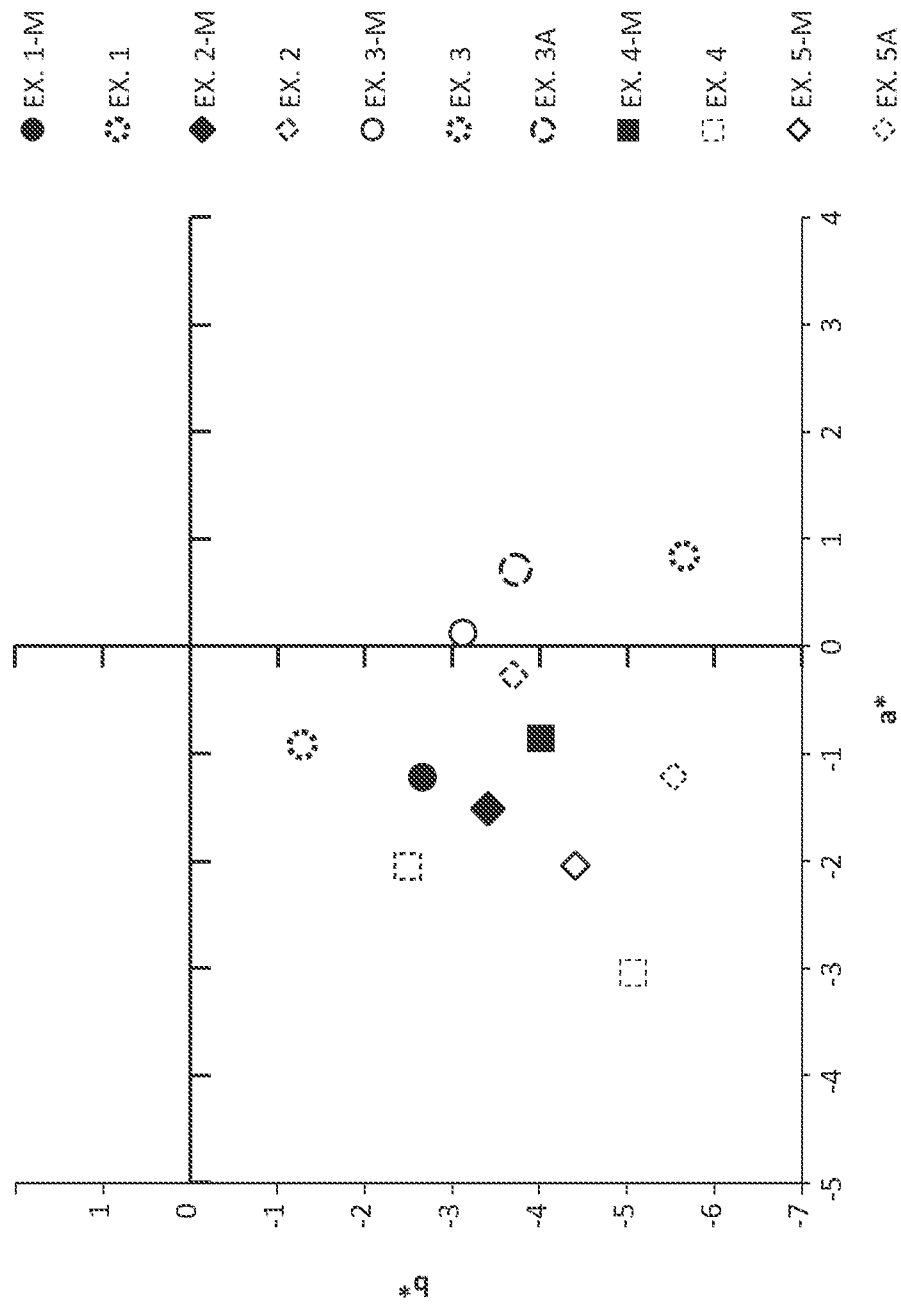


FIG. 7

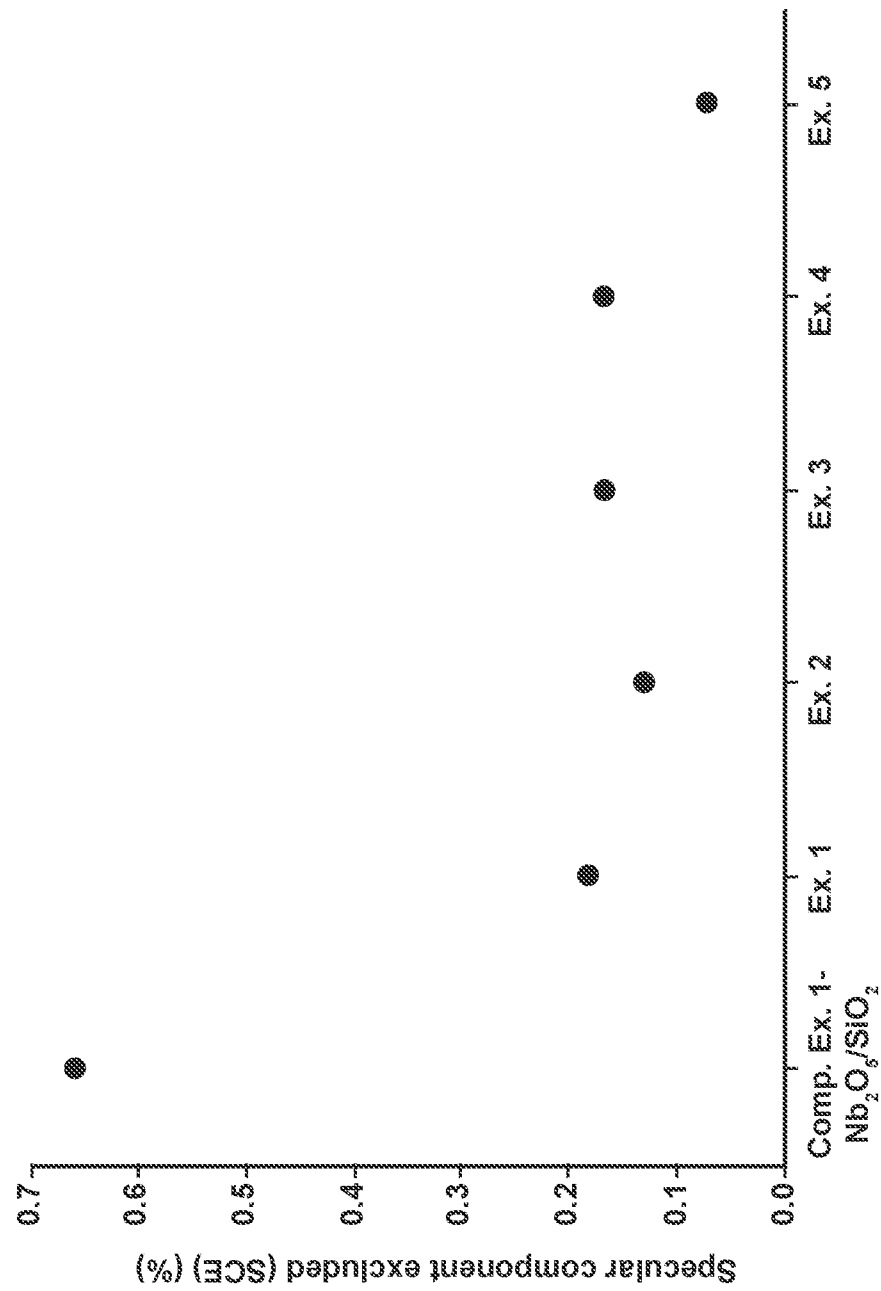


FIG. 8

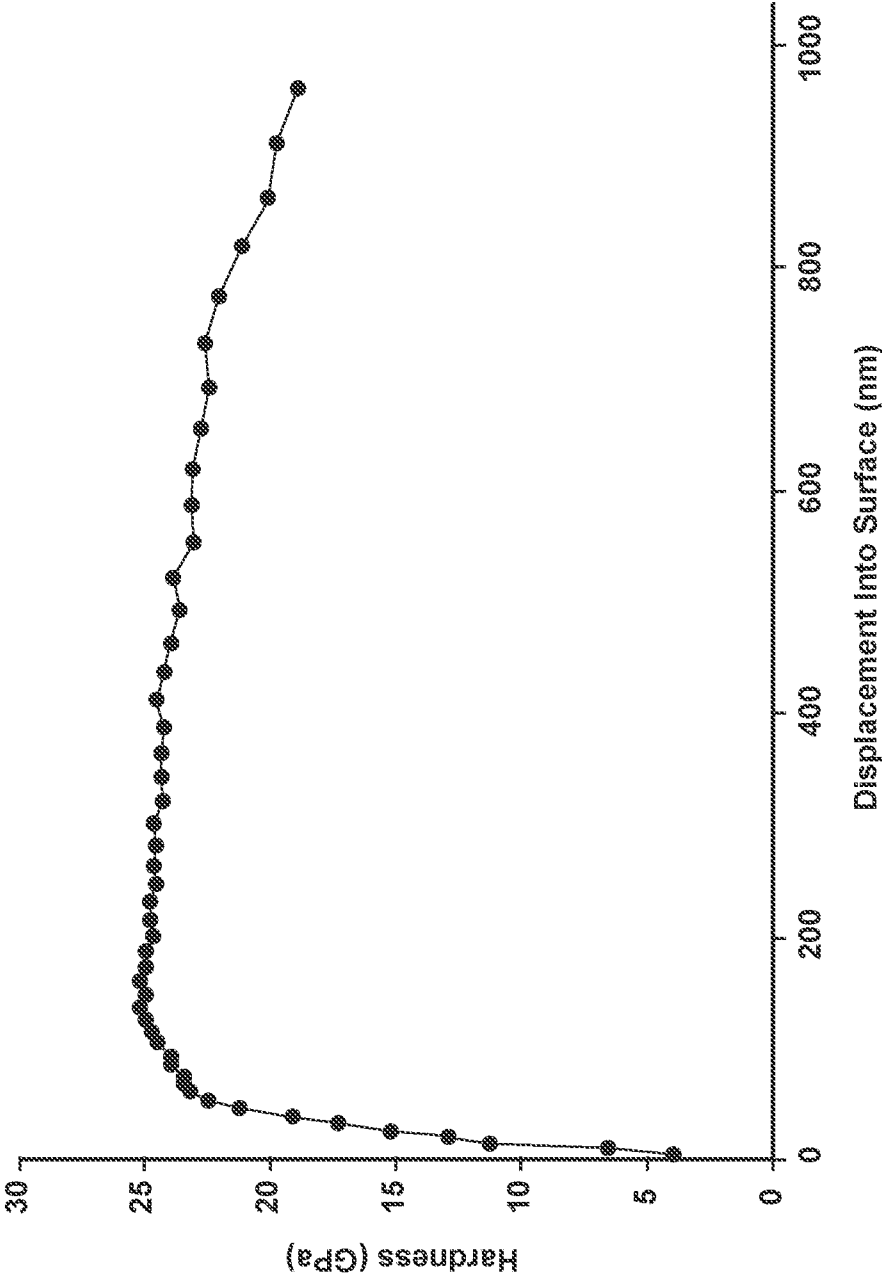


FIG. 9